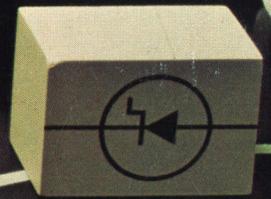


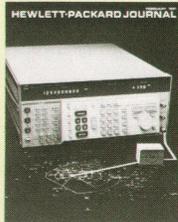
# HEWLETT-PACKARD JOURNAL



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## In this Issue:



The quality of a precision laboratory signal generator is measured by how little noise and spurious signals are present in its output along with the single-frequency signal that's supposed to be there. No noise at all is an impossible ideal, but the subject of this issue, Model 8662A Synthesized Signal Generator, comes as close to the ideal as any signal generator now available in its frequency range, which is 0.01 to 1280 megahertz.

Where are such super-clean, stable signals needed? Mostly in communications and radar transmitters and receivers, and for testing this kind of equipment. In these systems, information is superimposed on a single-frequency carrier signal by modulating the carrier's amplitude, frequency, or phase. A noisy carrier, one whose phase or amplitude jitters significantly, can severely limit the performance of a system. Phase noise tends to be particularly troublesome, and so the measurement of phase noise has become especially important. For phase-noise measurements, the 8662A is used as a stable source with which to compare the equipment under test. These measurements are done in the development laboratory, in production (where the 8662A's programmability makes automatic testing possible), and in maintenance.

In receiver testing, an important measurement is adjacent channel selectivity, aimed at finding out how well a receiver picks up a weak signal in one of its channels when there are strong interfering signals in adjacent channels. A clean interfering signal is needed for this test so the performance that's measured is the receiver's and not the signal generator's. Today, channels are being made narrower in an attempt to accommodate more customers in an increasingly crowded electromagnetic spectrum. The narrower the channels, the cleaner the test signal must be; hence the need for the 8662A.

Many applications lie above the 8662A's frequency range, but even in these cases, the 8662A's output can often be multiplied to the needed frequency and still be clean enough, even though its phase noise is multiplied, too. Our cover suggests an application like this. The 8662A feeds a step-recovery diode multiplier to provide the transmitted signal in a pulsed Doppler radar system. (In practice, a pair of 8662As would be used to generate both the transmitted signal and the receiver local oscillator signal). The radar scope in the foreground belongs to the U.S. Federal Aviation Administration's Oakland TRACON (Traffic Control). This radar actually operates at 1030 MHz, within the 8662A's frequency range. We thank the FAA for letting us photograph it.

-R. P. Dolan

# A High-Purity, Fast-Switching Synthesized Signal Generator

*When the lowest possible noise is a critical requirement for a programmable frequency source, this generator can do the job. Rapid switching and high output-level accuracy are two of its other advantages.*

by Roland Hassun

**R**EQUIREMENTS ON SIGNAL SOURCES used as test signals or directly in communications systems have escalated substantially. Spectral purity, which was barely mentioned in signal generator data sheets a dozen or so years ago, has now become a focal point in the description of the product. Indeed, it represents a major portion of the design and test efforts.

Many of the latest mobile communication systems rely on frequency switching executed in a few milliseconds. Test sources must therefore exceed this rate, while maintaining high levels of spectral purity.

Hewlett-Packard's answer to these needs is Model 8662A Synthesized Signal Generator, Fig. 1, a high-purity, high-accuracy, fast-switching, programmable source of frequencies between 10 kHz and 1280 MHz. The spectral purity of this new generator challenges the performance of mechanical and cavity-tuned generators such as the well known HP

8640B. At 160 MHz, for example, single-sideband (SSB) noise is  $< -144$  dBc/Hz at 10 kHz offset from the carrier and  $-113$  dBc/Hz at 10 Hz, with a broadband noise floor of  $-150$  dBc/Hz. Nonharmonic spurious signals are greater than 100 dB below the carrier. The key to this exceptional spectral purity is a new switched-inductance oscillator of novel design that produces a quiet free-running signal even before stabilization with phase-locked reference signals. The synthesized reference signal chain also has two separate crystal filter sections to clean up an already quiet 10-MHz crystal reference oscillator.

## Unprecedented Level Accuracy

The 8662A output level range is  $+13$  dBm (overrange to  $+16$  dBm) to  $-139.9$  dBm with a resolution of 0.1 dB. The internal microprocessor ensures that all levels between  $+13$  and  $-120$  dBm have an absolute level accuracy of  $\pm 1$  dB.



**Fig. 1.** Exceptionally low phase noise and spurious output make Model 8662A Synthesized Signal Generator suitable for such demanding applications as receiver adjacent channel selectivity measurements with closely spaced channels and low-noise local oscillator service. Fast frequency switching and sweep capability make the 8662A useful in frequency-agile and swept local oscillator applications. All functions are remotely programmable.

## Spectral Purity

Spectral purity is a measure of how much the spectrum of the output of a signal generator deviates from that of a pure sine wave. Factors affecting spectral purity are:

- Phase noise, manifested as random fluctuations of zero crossings in the time domain and spectrum spreading in the frequency domain
- AM noise, manifested as envelope fluctuations in the time domain and spectrum spreading in the frequency domain
- Nonharmonically related discrete sidebands, sometimes called spurs
- Harmonically related sidebands caused by harmonic distortion.

Phase noise is of particular importance in establishing the limits of many modern communications systems. Harmonic distortion, on the other hand, is not an important factor for the great majority of applications in communications systems. It can be substantially reduced by means of simple low-pass filtering.

AM noise levels are generally at least 10 dB below phase noise levels in most signal sources. Furthermore, many operating systems rely on angle modulation (phase or frequency) and are therefore not sensitive to AM noise.

Discrete sidebands can cause both amplitude and phase modulation but occupy a much more restricted portion of the spectrum than random modulation caused by random phase and amplitude fluctuations.

The total unwanted power occupying a particular communication channel consists of the sum of the power in the discrete sidebands plus the integral of the noise power in the channel bandwidth. Both components therefore need to be minimized.

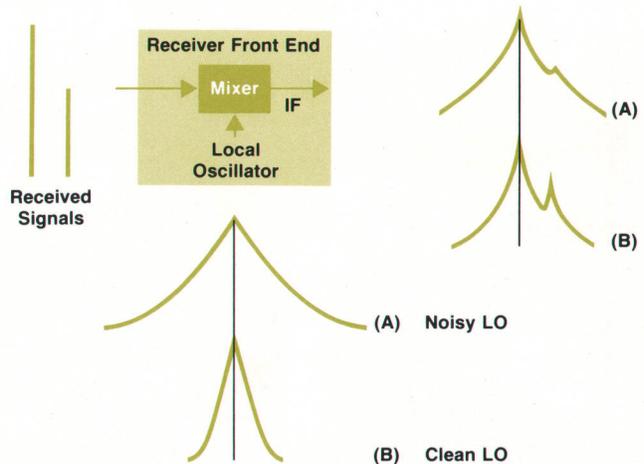
### Phase Noise

The spectrum spreading of the carrier that is caused by the existence of phase noise extends from less than 1 Hz offset from the carrier to wherever the effect of additive noise—thermal or active device noise—begins to dominate. This could be several MHz away from the carrier. Close-in phase noise is understood to include offsets within 5 kHz of the carrier, while far-out phase noise is understood to be that beyond 5 kHz.

Phase noise, or more generally, sideband noise (i.e., a combination of phase and AM noise), is responsible for limiting the resolving power of heterodyne systems such as FM receivers and spectrum analyzers. Resolving power in this case means the ability to detect a small signal in the presence of a large one (see Fig. 1).

Most mobile communications systems of the frequency multiplex kind have channel spacings that exceed 5 kHz. For example, 6.25-kHz channel spacing is now used in some areas having a high density of communications traffic. The system's ability to extract a desired low-level signal from an undesired high-level one (a nearby transmitter, for example) is limited by the sideband noise of the receiver local oscillator and the selectivity of the IF system. It is assumed in Fig. 1 that the received signals are spectrally pure. In fact, any sideband noise on the undesired high-level signal has the same effect as noise on the local oscillator.

Selectivity tests on high-quality mobile FM receivers require low-noise sources to simulate the undesired high-level signal.



**Fig. 1.** Sideband noise on the local oscillator output limits the resolving power of heterodyne receivers.

### Close-In Phase Noise

Many modern developments have created a need for good long-term stability and low close-in phase noise. Moving-target-indicator radars, navigation systems (e.g., Navstar), very-large-baseline interferometry and PSK (phase-shift keying) represent some of the applications where close-in phase noise plays a major role.

The measurement of close-in phase noise on RF and microwave sources is becoming a very fundamental one, because some crucial aspects of performance in the above-mentioned systems are related to this effect.

A common application for a low-noise signal generator such as the 8662A is as a reference source in phase-noise measurement setups.<sup>1</sup> The 8662A's combination of good long-term phase stability, excellent close-in phase noise and very good far-out phase noise makes it possible to test signal sources at offsets from the carrier ranging from fractions of a hertz to many MHz.

### Frequency Agility

Several new communications networks have an additional requirement for frequency switching on the order of several milliseconds. To provide dynamic test conditions for these systems, it is necessary for the test signal source to settle to a new frequency in somewhat under a millisecond.

The combination of this level of agility, low close-in and far-out noise and spurious sidebands represents an unusual engineering challenge. How these objectives were achieved in the 8662A is discussed in the accompanying article.

### Reference

1. D. Scherer, "Design Principles and Test Methods for Low Phase Noise RF and Microwave Sources," Hewlett-Packard RF and Microwave Symposium, 1979.

-Roland Hassun

This is accomplished by measuring the actual level with an accuracy of  $\pm 0.5$  dB at a large number of frequencies, determining the proper error correction, storing this informa-

tion in ROM, and then using it to correct the errors in output level as a function of frequency and attenuator setting. The 8662A's unprecedented level accuracy is essential for accu-

rate receiver sensitivity measurements.

Although primarily designed for high signal purity, the 8662A's indirect-type oscillator switches frequency with a typical 12 ms total switching time (to within 100 Hz). RF settling time is 0.5 ms. For testing frequency-agile receivers, a special learn mode may be used with the HP-IB\* programming bus to drive frequencies directly from the bus, with 500- $\mu$ s switching speed.

All other front-panel functions are programmable via the HP-IB, which is a standard feature. The microprocessor also provides powerful diagnostic and error routines to aid the user and service routines to aid in maintenance.

### Flexible Control

A major design objective of the front-panel layout was to improve measurement efficiency so that engineering and production test productivity could be increased. Key functions are grouped centrally. Frequencies are key-set to 0.1 Hz (or 0.2 Hz) and levels to 0.1 dB resolution. Values can be incremented or decremented with up/down keys or a rotary knob after keying in the desired step size. A store/recall function allows up to nine complete front-panel control settings to be retained and recalled singly or in a sequence of up to 10 steps.

Most increment and sequence steps can be triggered by rear-panel inputs. A series of pins available on a rear-panel connector allows certain commands to be executed when one of the pins is connected to ground (a debounce circuit is provided internally) or pulsed with a negative-going TTL-compatible pulse of at least 5- $\mu$ s duration. This allows outputs to be tied back to inputs directly, thus creating a sequential system, or through decision-making logic. For example, if the sweep output is tied to the step-up pin, the whole frequency range of the 8662A can be sequentially swept in specified increments. If a detector circuit and some logic are also used, then the sweeping action can be stopped whenever a signal is detected.

Powerful sweep capability that preserves synthesizer stability, resolution, and accuracy makes the 8662A ideal for characterizing high-stability components such as crystal filters. Start/stop or span sweeps can be selected. Five key-set markers plus linear or log sweep are available. By using the sequence function, multiple sweeps can be observed simultaneously.

Full signal-generator capability is provided, with high-performance AM and FM modulation. AM rates to 40 kHz are possible depending on modulation depth and carrier frequency. FM deviations to 200 kHz and rates to 100 kHz are available for external modulation inputs. A 400 or 1000-Hz internal source can be selected.

### Architecture

The architecture of the 8662A reflects the major design goals, which included low phase noise close to the carrier (less than 5 kHz offsets), low phase noise far from the carrier, submillisecond frequency switching speeds, spurious sidebands more than 90 dB below the carrier, 0.1-Hz frequency resolution, and quality modulation capability. The phase-locked loop approach to frequency synthesis was chosen because these objectives could be met with a lower level of product complexity. Fig. 2 is the 8662A

\*Compatible with IEEE 488.

block diagram.

Divide ratios have been chosen so that noise on any of the reference signals going into the phase detectors does not undergo multiplication by more than 2 at the output. The use of fractional-N divider techniques (see article, page 12) allows the achievement of a specific frequency resolution while maintaining a wider loop bandwidth (leading to higher switching speed) than would be possible without the use of fractional-N. At the same time, the divide ratio is kept small.

Sidebands caused by reference signals leaking into the VCOs (voltage-controlled oscillators) are kept below -100 dBc on the output signal in the majority of cases. This is accomplished by filtering, isolation, and shielding.

The provision of frequency modulation required the addition of two phase-locked loops in the block diagram. One loop is used to generate the frequency modulated signal by applying the modulating signal to the VCO. The loop bandwidth is less than the lowest modulating signal frequency. The other loop is used to sum the modulated signal into the system.

Fig. 3 shows typical 8662A single-sideband phase noise. Below 10 kHz, phase noise of the reference section dominates. From 10 to 500 kHz the reference loop and sum loop determine the phase noise performance, while beyond 500 kHz the sum loop oscillator is the dominant phase noise source.

This noise profile indicates that the HP 8662A is not only an RF synthesizer with exceptional close-in noise performance, but that it can also compete well at farther-out offset frequencies where cavity oscillators were traditionally far superior. With its switching speed of 500  $\mu$ s (RF settling time), the HP 8662A meets the usually conflicting requirements of low phase noise and high frequency agility.

### Assuring Reliability

The required improvements in signal generator spectral purity and switching speed have made the 8662A an extremely complex product. The design philosophy for complex products must include reliability and serviceability to achieve operating cost levels acceptable to the user. Therefore, reliability and serviceability goals were an integral part of the early 8662A definition along with performance and cost objectives. Reliability was the subject of significant planning throughout the course of the project. Management support at all levels was inspirational in steadfastly pursuing a goal that is difficult to measure.

A number of steps were taken to make a substantial improvement in reliability. A series of educational sessions for the project team were held by the corporate and divisional reliability groups. The strong commitment of all team members to reliability was a significant factor in maintaining the emphasis over a period of several years.

The main thrust of the reliability effort in the development phase was the creation of an environment within the product that would favor component longevity. It was decided very early to limit semiconductor junction temperatures to less than 110°C when the ambient temperature is at the specified maximum of 55°C. Junction temperature is a parameter that is directly related to semiconductor failure rate. It was measured by making body temperature mea-

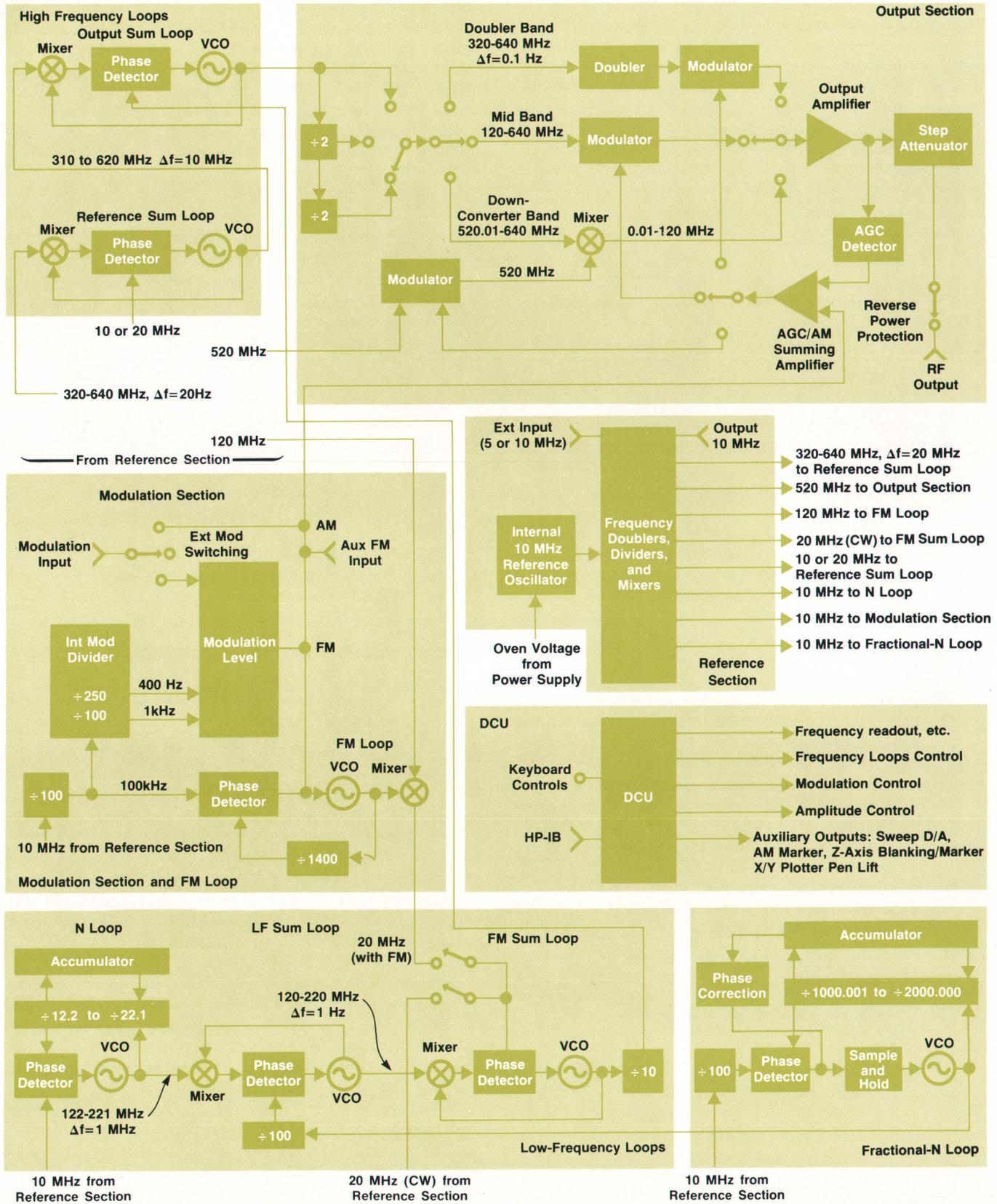


Fig. 2. 8662A block diagram. The phase-locked loop method of frequency synthesis meets the performance objectives with minimum product complexity.

measurements using thermocouples on well over 100 components at several stages throughout the development cycle. Junction temperature was then computed with the knowledge of the power dissipated in the device and its published junction-to-body thermal resistance. The goal was met with the exception of a microwave transistor chip used in the output amplifier, whose junction temperature can reach 125°C (computed) in the very worst case. The use of a high-efficiency switching regulated power supply that saves approximately 70W and a carefully planned thermal design approach were necessities in achieving the junction temperature goal.

Another step taken was the reduction of electrical stress on the components used. Power dissipation, voltage and current were checked on all transistors and passive components. The reliability group helped establish safe derated limits to which the designers adhered. Design margins on such crucial parameters as phase-locked loop acquisition ranges were made very substantial.

Humidity and condensation tests carried out in the course of a battery of environmental tests revealed some harmful chemical action. Growth of a clear, amorphous, nonconducting substance gave rise to intermittent contact between printed circuit board connector fingers and their sockets. The microprocessor-based controller was especially vulnerable to this, since missing a single pulse can change a legitimate instruction to an unintelligible stream of information. A task force consisting mainly of product assurance and printed circuit board processing groups traced the problem to contaminants in the water used in the wash cycle. They were eliminated and the problem went away.

A number of assemblies containing novel designs were put through life tests. This included prolonged periods of operation at elevated ambient temperature (55°C). Two of four switched reactance oscillators exhibited identical failure modes on the tenth and eleventh days of testing. A thin layer of insulation was punched through causing a mal-

function. The condition was corrected. The life tests proved very useful in identifying a number of systematic problems that generally only show up after lengthy periods of time and may not be diagnosed as problems when not viewed in the context of a disciplined test.

Furthermore, a sufficient number of prototypes were built, operated almost continuously, and exercised whenever possible to uncover weaknesses. This intensive search for problems proved quite effective.

Most of the semiconductors used in the product are burned in according to a program developed by HP's Stanford Park Division product assurance group. A 5:1 reduction in failure rate has been observed in a pilot program. Failures detected are carefully analyzed and when systematic patterns emerge, the suppliers of the faulty devices are notified.

### Acknowledgments

The 8662A was a large project that spanned a considerable period of time. Many people have contributed to it in various disciplines. The reliability of the product has benefited both in planning and execution from the close involvement of the Stanford Park Division Reliability Group under the leadership of Julius Trager, especially Randy White and Charles Sallsey. Bill Whitney's leadership and Gary Sprader's inputs were very valuable in the field of serviceability. Introduction to manufacturing was planned and organized by Bob Ickes. The long involvement of Marilyn Lawrence and Tom Cottrell as test technicians, together with the assembly team of Shirley Flock and Edna Fleck, was much appreciated by the R&D team. Marketing activity was managed by Mike Gallagher. Original product definition benefited from the inputs of Ned Barnholt, Marc Saunders and Wally Rasmussen. The development project took place in the Stanford Park Division R&D lab managed by John Page and was part of Brian Unter's R&D section responsibility. I also wish to acknowledge John Hasen's many contributions as a member of the design team, especially in the later stages of the project.

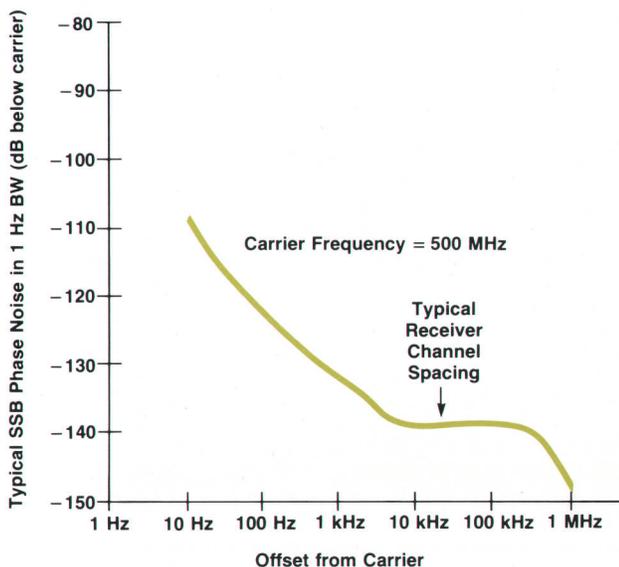


Fig. 3. Typical 8662A phase noise performance.

### Roland Hassun



Rolly Hassun received his BSEE degree from the Politecnico di Milano in 1960 and his MSEE degree from California State University at San Jose in 1963. He's also done graduate work at Stanford University. After joining HP in 1961, he worked on the 410C Voltmeter, did studies on transistor noise, designed synthesizers, and ultimately served as project manager for the 8662A Signal Generator. He's lectured on synthesizers and spectral purity on three continents in three languages. This article is his third contribution to the HP Journal. A member of the IEEE, the IEEE Computer Society, and AFCEA, he's vice chairman of the program committee for the IEEE's 1981 western convention. Rolly enjoys tennis, bridge and spy novels. He's interested in world affairs and has served as an officer of a large philanthropic organization, receiving its leadership award.

# Digital Control for a High-Performance Programmable Signal Generator

by Hamilton C. Chisholm

**A** CURRENT PRODUCTION INSTRUMENT, the Hewlett-Packard 8660A Synthesized Signal Generator, successfully demonstrates the concept of keyboard control of a signal generator. By means of the Hewlett-Packard Interface Bus (HP-IB),\* it also provides a means of solving many instrumentation problems calling for remote control. This previous development served as a guide in the planning of the 8662A Synthesized Signal Generator. Many enhancements were developed to provide full control of all parameters. The panel arrangement provides the operator with easily understood parameter control. Interaction with a responding parameter display reinforces the learning of short key sequences. Where function control is not obvious from the front panel, a pullout card beneath the instrument quickly provides assistance.

The 8662A is basically a signal source of sinusoidal frequencies with exceptional purity. With the addition of amplitude control and selectable amplitude and frequency modulation, the source becomes a signal generator. With step time and step frequency control, the generator is enhanced with frequency sweeping capabilities.

## Controller Design

The block diagram of the digital control unit of the 8662A is shown in Fig. 1. The controller has latched driver outputs for eleven digits of frequency from 10 kHz to 1.28 GHz with 0.1-Hz resolution (0.2-Hz resolution above 640 MHz). Four digits of amplitude in either dBm, mV, or  $\mu$ V units are also latched out for the control of electronic and electromechanical attenuation. Modulation drive in the form of two binary control words is latched out for either AM or FM. The HP Interface Bus signals are conducted to the rear panel. An additional set of external inputs can be used to control the functions increment up, increment down, start sweep, stop sweep, single sweep, and sequence. Also, a set of lines from the linear circuits provides the controller with information pertaining to malfunctions of these circuits. All told, 132 lines are exercised by the digital control unit.

The choice of the 6800 microprocessor for the 8662A

control unit was based on the 6800's advanced 8-bit concept, a system of components that includes the 6820 Peripheral Interface Adaptor and compatible ROM and RAM devices, and availability within HP of suitable assembler and loader programs that operate in HP computers.

The 8662A control system is designed with modularity for servicing in mind. Access to all circuit boards is assured by clever configuration of the card frame and by a tilt-down front panel. The microprocessor circuitry and a few components for signature analysis are on the processor control board. Two boards with 12 kilobytes each of  $1K \times 8$  PROM constitute major memory. The RAM board with 2 kilobytes of CMOS RAM provides nonvolatile memory for variables, stored parameters, and stored information for nine blocks of front-panel data (more about this later).

An input board provides malfunction inputs and the interface to the keyboard and the set of external inputs. Two output boards contain the latched drivers for frequency and modulation. The display board contains latching LED numeric displays and latched drivers for backlit numeric nomenclature. Readout control is non-scanning to avoid any radio frequency interference. All of the circuitry necessary for the HP-IB, including 2 kilobytes of program memory, is on a card that can be removed from the controller without impairing normal local-mode operation.

The keyboards have specially designed keys to meet requirements of random positioning, low profile, minimum spacing, and control LED lighting. The keystroke is short and has positive tactile feel. Gold plated, bifurcated spring contacts make reliable, wiping contact with printed circuit pads on boards that are readily serviceable.

## Keyboard Operations

The central portion of the keyboard, on the sloping panel, contains the major function qualifier keys and the numeric keypad. The expected key sequence is left to right: selection of function, then numeric data, followed by execution with a units key such as MHz. The numbers are visible in the function display as entered. When the units key is held down, the justified entry is held visible. This is useful in the

\*Compatible with IEEE 488-1978.

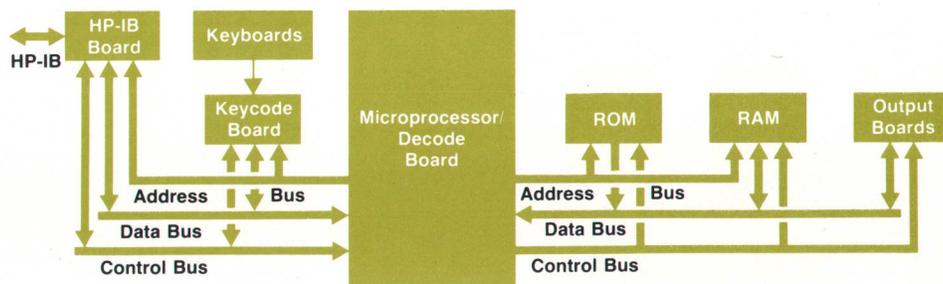


Fig. 1. Digital control unit of the 8662A Synthesized Signal Generator exercises 132 control lines.

# 8662A Power-On and Self-Test Sequences

by Albert W. Kovalick

With the introduction of microprocessor-based "smart" instruments, many conveniences were gained. However, some features of worth were lost. A typical instrument without a smart controller has the ability to remember user settings by virtue of its front-panel mechanical switches and dial settings. Most smart instruments, on the other hand, require the user to key in most front-panel settings each time power is switched on. An alternative is to use the HP-IB and program the instrument externally. For simple stand-alone applications, however, manual initialization of the instrument is a drawback.

The 8662A Synthesized Signal Generator solves this problem by using a CMOS RAM powered by a battery to keep a record of all front-panel settings. When the user turns off the synthesizer or the power fails, the existing front-panel setting is saved. When power is restored the last saved front-panel setting is restored.

## Power-on Sequence

When the 8662A is switched on, a hardware power-on circuit resets all hardware functions and causes the controller program to begin. Before the settings are restored a checksum is computed from the saved front-panel data. This is compared to a reference checksum. If both checksums match, a software routine restores all frequency, modulation, and amplitude settings. If the checksums disagree, RAM data has been altered. This is unlikely, but it can occur if the battery discharges. In this event, the first valid front-panel setting from the store/recall memory is recalled. If all nine settings contain altered data then a default setting of 100 MHz and -30 dBm is used.

## RAM Testing

Testing of the entire 2K bytes of RAM is performed each time the instrument is switched on. This power-on RAM test checks for stuck bits in every RAM location without destroying any RAM data. Before the test can begin, a small section or kernel of RAM is tested. This kernel is needed to perform the larger 2K-byte test. Each bit of RAM is now tested for the ability to toggle. If any bits are found faulty, a user code is displayed to indicate this. By use of a special function code, a user may access this same test and run it when desired.

A second, more extensive test is accessible by calling a routine in the diagnostics ROM. It is different from the simpler test in three ways. First, it checks for the case of multiple chips enabled. Second, it tests for CMOS memory fade problems. Last, it tests for row/column decoding errors internal to the chips. This test is exhaustive. It runs for about 1.5 minutes and pinpoints any faulty chips.

The test for multiple chips enabled must be performed before decoding problems can be detected. If more than one RAM chip is enabled, a read or write will affect more than the desired RAM. The test is structured as follows.

1. All memory cleared to zero
2. Store a single RAM ID number in each RAM. RAM 1 (0-255) has a solitary 1 stored. RAM 2 (256-511) has a 2 stored and so on (see Fig. 1a).
3. The contents of the RAMs are now summed individually. If the sum of each RAM is equal to its original RAM ID number, then no RAMs are selected out of their address range.
4. If one or more RAMs are selected out of their address space

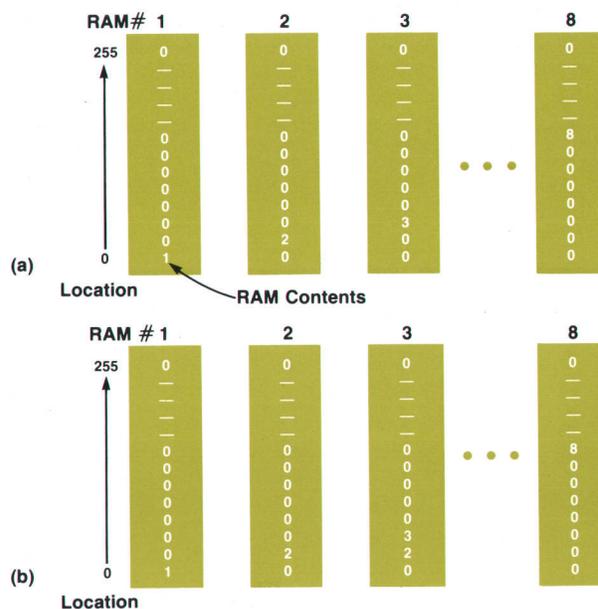
then the RAM data will not sum to the value of the RAM ID number (see Fig. 1b). The bad chip is now identified and the faulty RAM number is displayed.

If no multiple read/write problems are detected then an exhaustive test for internal row/column decoding is performed. First, a memory location is set to a known value. Next, all remaining locations in each RAM are checked for alteration. If any data alteration is found, then the bad RAM is identified. Each memory cell is similarly tested.

Finally, a data fade test is performed. Due to the inherent capacitive memory effect of CMOS memory, it is possible to store a 1 or 0 even though a given RAM cell is bad. This is a temporary memory effect, and in time, the data fades away because of leakage. We detect a fade problem by testing data over a period greater than one second.

## ROM Testing

The 8662A has 26 ROMs that contain the operating program. The traditional method used to test a ROM is by use of a checksum. The reference checksums are usually stored in known locations and compared to calculated checksums for each ROM to prove ROM validity. This technique has the disadvantage of storing the reference checksum. If it is stored in a known location outside the ROM, then when a ROM is modified, its reference



**Fig. 1.** (a) To detect multiple chips enabled, each RAM has only one number stored. The value is the same as its RAM ID number. Each stored value is at a different location to avoid overlap. (b) Example of multiple chip selection. RAM 3 was selected during RAM 2 addressing due to a faulty chip select decoder. The sum of RAM 3 data is 0, not 3 as it should be. Because of inherent wired-ANDing on the RAM data bus, the sum of RAM 2 is 2, even though RAM 3 is selected.

checksum must also be changed. Hence, two ROMs may need changing. On the other hand, if each ROM has its checksum stored within it, then an exact location is required and this may interrupt the program code.

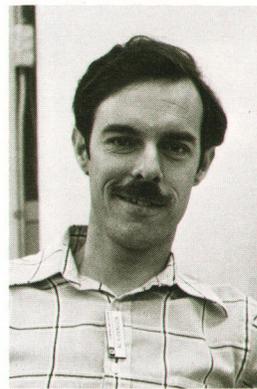
We have chosen to allocate the negative value of the checksum dynamically. Suppose a sequence of assembly language code could be produced that would not affect program operation and would rarely, if ever, be produced by a programmer. A branch around a NOP (no operation) falls into this category.

```
--
--          PROGRAM CODE
--
BRA +3
NOP
--
--          PROGRAM CODE
--
```

Once the program development is almost complete, this two-line code segment is inserted roughly into the middle of each ROM. After assembly is complete the machine code is run through a second program to locate the two-line segment. Next, this program computes the checksum of all ROM data excluding the NOP. The NOP is then replaced by the two's complement of the checksum. The controller program is not affected by this change

due to the branch. Computing the checksum of a given ROM yields zero as a result if all data is valid. The programmer never needs to worry about the value of the checksum or the NOP location. To allow for easy ROM identification the actual value of the total computed checksum can be one for ROM #1, two for ROM #2, and so on. This allows for easy detection of misloaded ROMs.

#### Albert W. Kovalick



Al Kovalick joined HP in 1974 after receiving his MSEE degree from the University of California at Berkeley. He's designed printer drive circuitry for handheld and desktop calculators and contributed to the design of the controller software and power supply of the 8662A Signal Generator. He's named as an inventor on two patents and three pending patents. Al was born in San Francisco and now lives in Santa Clara, California. His wife, who works in HP's R&D labs as a programmer, has also contributed an article to the HP Journal. Al is active in his church and enjoys reading, woodworking, racquetball, and recreational mathematics.

frequency mode where the display may be configured for sweep display while a new parameter is entered. Should the operator begin an entry but not complete it, the display can be restored by striking any function select key.

The **INCR SET** key is common to all function keys and a function key qualifies its use in entering increment values. The justified value may be viewed on entry by holding the units key down. An increment value may be viewed at any time by selecting the function, then holding the **INCR SET** key down.

The right-hand position of the keyboard contains modifiers in the form of increment up and down keys and a rotary control for manual tuning. The increment up and down keys are qualified by the selected function. Holding either key down will cause a succession of increments at a rate of two per second. The rotary **RESOLUTION** control is enabled for every new function by pressing either the  $\times 10$  or  $\div 10$  key. Holding either of these down will enable blinking of a digit that denotes the resolution digit to which the rotary control will apply. The digit may be moved by repeatedly keying  $\times 10$  or  $\div 10$  to get ten times more or less resolution.

The increment value previously entered via the **INCR SET** key may be used by the rotary control as its entry value. This mode is enabled by pressing the blue key and then the  $\div 10$  key, which has the shifted function **INCR** printed beside it. Another useful mode is the separation of rotary control operation from the increment key operation with respect to function. For example, while in the amplitude mode, the blue key and shift key **HOLD** ( $\times 10$ ) are pressed in succession. Then when frequency is selected as the operating function, the amplitude may be adjusted with the rotary control and the frequency incremented with the increment up and down keys.

#### Sweep Control

The left-hand keyboard contains all the sweep parameter keys. Either a start/stop sweep or a span-type sweep may be selected. Parameters are entered, for instance, by keying **START FREQ**, numerics and units.

The start/stop sweep may be reversed by giving start a larger frequency value than stop. The sweep step size and step time keys indicate the selected value with integral LEDs. Once selected, the values are remembered. A change from span to start/stop sweep, with different step size and time values, will be indicated by the LEDs in the keytops. Execution of **AUTO** or **SINGLE** sweep will cause a split display in the frequency window, five digits for each of the two frequency parameters. When **MANUAL** sweep is selected, a full eleven-digit sweep frequency display is presented. Control of the sweep is provided by dedicated use of the rotary knob in the right-hand portion of the keyboard. Any signal generator parameter value may be changed while in the sweeping mode.

Up to five digital sweep frequency markers are selectable. Each marker is entered as a frequency. The rear-panel output for sweep markers provides Z-axis beam intensifying potential to give a bright CRT spot on an oscilloscope. Each spot may be identified on the CRT by holding the selected marker key down. Each marker may be moved on the CRT by means of the increment keys or the rotary control. When a marker key is held down, its frequency value is displayed.

#### Front-Panel Storage

To ease user operation of the 8662A, nine front-panel configurations can be stored in memory. Each stored configuration includes every parameter set on the front panel. Thus at any time, any of several totally different panel configurations can be recalled. This helps to reduce test setup time.

Coupled with the store/recall feature is a sequence operation. A sequence is the order in which the user desires to recall previously stored settings. For example, assume there is a linear sweep in store 1, a logarithmic sweep in store 3 and a frequency modulated carrier in store 7. These may be useful for a given series of tests. The sequence 137 can now be stored in the sequence memory, and each time the **SEQ** key is pressed the next front panel, as ordered by the sequence memory, will be recalled.

### Status Indication

The 8662A features a **STATUS** key, which is LED-lighted to signal the operator. Whenever it lights up and the key is pressed and held, a double-digit code appears in the frequency window. The code can be interpreted by referring to the pullout card beneath the instrument. Status messages may concern the condition of the crystal oven temperature, or indicate that an external oscillator standard is being used. Operator guidance messages are typically concerned with parameters out of range for the operating conditions.

The status indicator flashes for malfunctions detected internally. Examples are a loop unlock condition or a fault detected by a circuit monitoring a set of interface lines. The latter provide extensive information about approximately 80 lines passing between controller and mainframe circuits. These give early indications of circuit or cabling failures.

### Servicing

The operator may call for a check on ROM or RAM with a special function key sequence. The ROM test (see page 9) is based on checksum routines and responds in case of a ROM IC failure with a double-digit code in the display, defining the failed part. The RAM test will do the same for some bit-type failures. More subtle failures require more detailed testing, which is available in servicing routines. The latter are part of a switch selectable set, which also includes routines for signature analysis testing with the HP 5004A Signal Analyzer. Basically, control unit servicing is performed using signature analysis. For extreme conditions where the instrument does not respond to power-on, a fundamental free-run test permits checks of the microprocessor board, which is the key to further operation. This can be done without any other boards in the system, thus aiding discovery of stuck address and data buses and control lines. With a correctly operating processor board, the special diagnostics ROM and a program select switch on the board are used to select a routine to stimulate the other system boards. Signatures at significant circuit points quickly give direction to the service person and lead to discovery of the offending component on the failed system board.

### Production Testing

Production testing of the 8662A control unit uses signature analysis techniques almost exclusively. These techniques are aided by using an HP 9825 Computer as memory for all the circuit mode signatures and as a testing guide. The technician instructs the computer with inputs

defining the system board and the integrated circuit under test. As the device pins are probed, the computer reads the input signature via the HP 5004A with a special modification. A comparison is made with the known good signature in memory. An audible beep announces that the signature is good and the technician can proceed to the next node without looking away from the circuit. When an errant signature is encountered, the computer prints out the node location on its paper tape.

A further testing development uses the computer with a special multiplexer that can select any one of over 200 lines. Suitable cabling connects all the control output interface lines into the multiplexer. Computer programs are accessed for a series of tests that automatically monitor all the cabled lines and record information on any failures. This test has special merit, since it tests driving circuits, connectors, and cables in the signal path, any of which can experience difficulties in the assembly operations.

### Acknowledgments

Many people contributed to the concept and design of the control unit, which includes the front-panel display and keyboard arrangement. The key members of the design staff and their contributions were: Walt Jimison for major portions of the hardware design and associated software, Han Park for major software contributions to the control of the display, frequency sweeping, and sweep markers, Dan Derby and Jim Stewart, industrial designers, for their important contributions to the subtleties of panel design, Bill Thomas, production engineer, for a major effort in applying signature analysis with calculator control to production testing, and Lloyd Marrugg, production engineer, for devoted effort in the transfer of the controller from engineering to production, effectively coping with the training of personnel. To Bill West goes a special thanks for a superlative effort in designing the keyswitches now used extensively in Hewlett-Packard instruments.

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#### Hamilton C. Chisholm



Ham Chisholm received his BEE degree in 1948 from the University of Minnesota. He designed some of the first solid-state counters in 1954 and some of the first integrated circuit counters in 1968. He's published several papers and is named inventor on several patents. With HP since 1966, he worked on the 5590A Nuclear Scaler and served as project leader for the digital control sections of the 8660A, 8660C, and 8662A Signal Generators. He has served in the U.S. Air Force as a flight navigator and is a member of the IEEE. Ham enjoys gardening, photography, camping, and skiing. A native of Minneapolis, Minnesota, he now lives in Los Altos, California. He and his wife have a son and a grandson.

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# Low-Noise RF Signal Generator Design

by Dieter Scherer, Bill S. Chan, Fred H. Ives, William J. Crilly, Jr., and Donald W. Mathiesen

IN THE RF DESIGN of the 8662A Synthesized Signal Generator, novel techniques had to be developed to combine low phase noise and low spurious signals with the usually conflicting goal of high frequency agility. The design was governed by the following objectives:

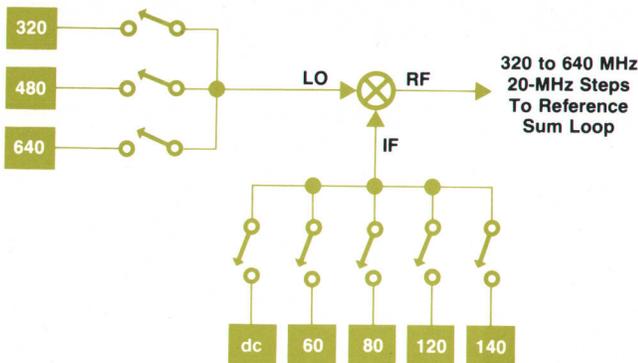
- Excellent spectral purity. Phase noise and spurious signals were to be low enough to allow, for example, receiver out-of-channel testing previously only possible with very pure cavity-tuned signal generators.
- High frequency agility. RF settling was to occur in less than 500  $\mu$ s.
- Economic frequency resolution. 0.1-Hz resolution was to be achieved with a minimum number of loops and minimum parts count.

Fig. 2 on page 6 shows the basic blocks of the resulting RF design. These include the following functional blocks:

- The reference section
- The reference sum loop
- The output sum loop
- The low-frequency loops
- The fractional-N loop
- The doubler, dividers and down-converter of the output section.

All frequencies are directly or indirectly generated from a 10-MHz crystal oscillator or an external 5 or 10-MHz reference source. The reference section transforms the 10-MHz reference signal into an RF reference signal that can step from 320 to 640 MHz in 20-MHz steps.

In the reference loop this spectrum is filtered and expanded into a 310-to-620-MHz range with 10-MHz steps. The output sum loop combines this with a 10-to-20-MHz signal with 0.1-Hz steps generated in the low-frequency loops, yielding the 320-to-640-MHz baseband with 0.1-Hz resolution. This band is then heterodyned, divided down and doubled to produce the 10-kHz-to-1280-MHz output of the synthesizer (see article, page 22).

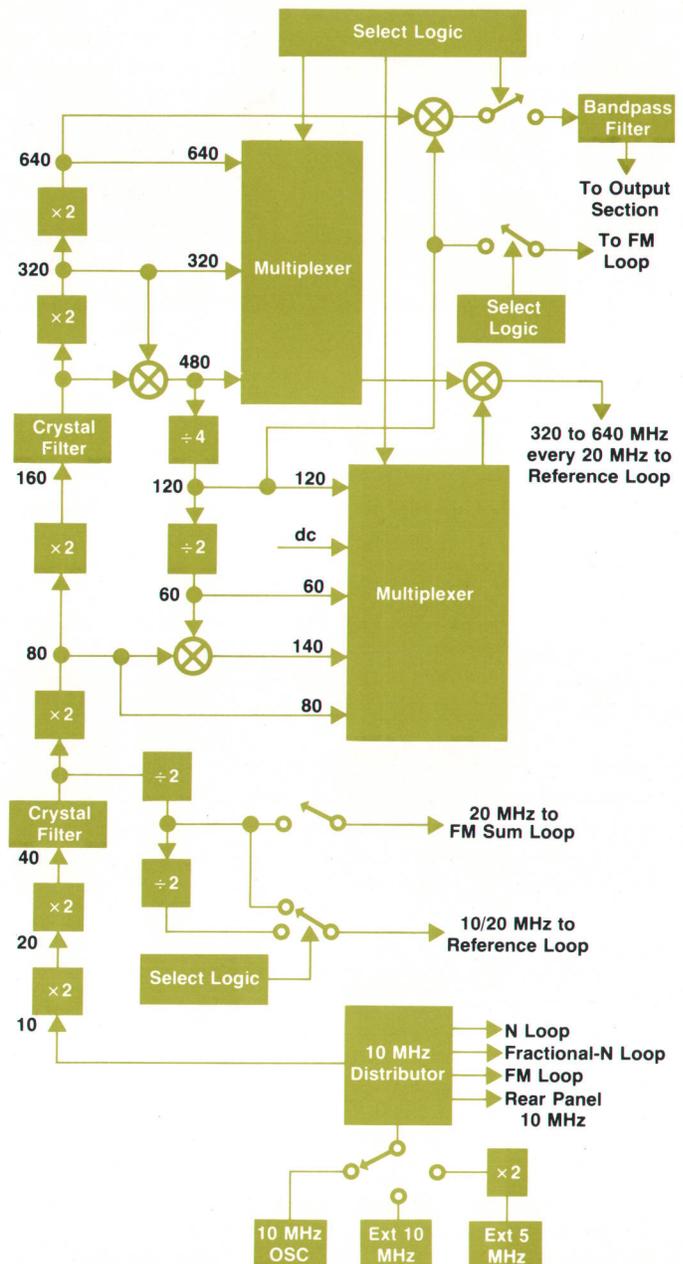


**Fig. 1.** The reference section directly synthesizes low-noise reference signals for the 8662A's phase-locked loops. The 320-to-640 MHz band is generated with a mixer and eight frequencies, as shown.

## Direct Synthesis Reference Section

The reference section provides the following group of frequencies:

1. 320 to 640 MHz every 20 MHz.
2. A switched 520 MHz to the output section down-converter.
3. Switched 20 and 120 MHz to the FM sum-loop.



**Fig. 2.** 8662A reference section derives various frequencies by multiplying, dividing, and mixing the output of the internal crystal reference oscillator or an external standard.

4. A selectable 10 or 20 MHz to the reference sum loop.
5. 10 MHz distributed to five other sections.

It was considered important that these frequencies be obtained with as low a noise contribution as achievable and with undesired signals down 40 dB at the 320-to-640-MHz reference output.

As Fig. 1 shows, the 320-to-640-MHz band may be generated with a mixer and eight frequencies. Using dc allows the 320, 480, or 640-MHz signal to pass through the mixer. Otherwise, two RF frequencies are generated ( $f_{RF} = f_{LO} \pm f_{IF}$ ), and the undesired frequency is eliminated by the reference sum loop. Fig. 2 explains the generation of reference signals in more detail.

### Noise and Undesired Signals

Particular care was exercised in the design of the amplifier and multiplier stages immediately following the crystal oscillator to keep from degrading its noise performance. The amplifiers and doublers at higher frequencies are not so critical since the phase noise of the 10-MHz standard is increased by 6 dB each time the frequency is doubled.

The multiplier selected is essentially a full-wave rectifier circuit using Schottky diodes. This arrangement was selected for the repeatability of low-noise performance, inherent rejection of the driving frequency (alleviating some filtering problems), and convenience in generating a frequency at every octave of 10 MHz.

The amplifiers operate with low currents and high voltages to keep the  $1/f$  noise current of the device low. RF emitter degeneration decreases device nonlinearity, which partly prevents  $1/f$  noise from being converted to the signal frequency.

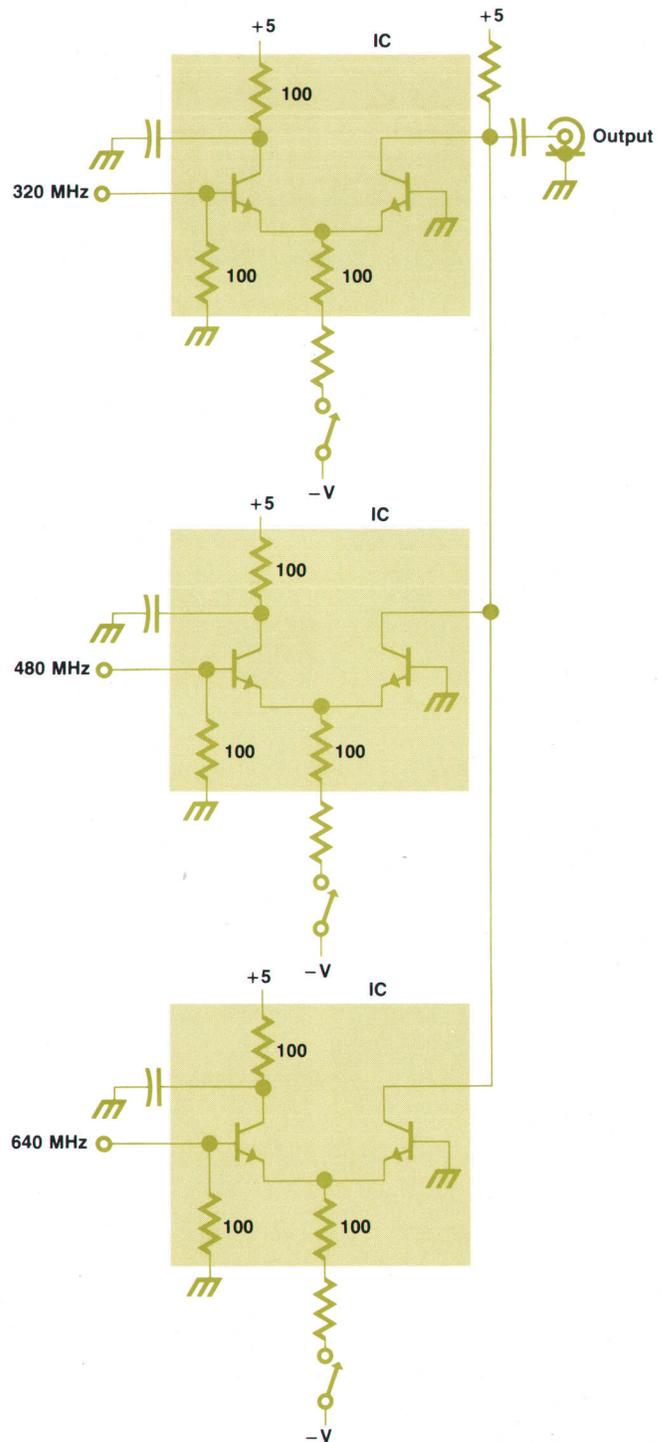
The reference block has two stages of crystal filtering at 40 and 160 MHz. The filters serve the dual purpose of removing 10 and 20-MHz sidebands not rejected by the doublers and filtering the multiplied noise of the frequency standard beyond approximately  $\pm 0.008\%$  of center frequency. Multiplying 10 MHz to 640 MHz would result in a 36-dB phase-noise increase. The crystal filters must suppress the 10 and 20-MHz sidebands such that these sidebands on the 520-MHz output are 90 dB below the carrier, since they would be translated directly to the output in the heterodyne band. Two-pole monolithic quartz filters were chosen for their compactness and low cost.

A problem associated with the use of these narrow-band filters is their high susceptibility to vibration. To combat this problem, the filters are shock mounted on a separate, small circuit board.

Sources of noise that contribute to the residual noise of the reference section include the following:

- Additive noise and  $1/f$  noise in transistors, most prominently in the first stages of multiplication
- Leakage currents in capacitors and Schottky diodes
- Thermal effects on various materials
- Phase changes caused by cables and connectors
- Crystal filter noise and microphonic noise.

Noise of the reference section is typically  $-110$  dB below the carrier at 10 Hz offset with the noise floor approximately  $-148$  dBc at 10 kHz and farther out.



**Fig. 3.** The higher frequencies in the reference section are switched by a form of ECL multiplexer using several monolithic differential pairs connected to a common collector resistor.

### Switching

It was necessary to find ways of switching frequencies with a minimum of complexity since the reference section uses direct synthesis. ECL multiplexers were found to have inadequate pin-to-pin isolation. Discrete forms of PIN diode switches require multiple diodes and drivers all properly shielded. A form of ECL multiplexing using several

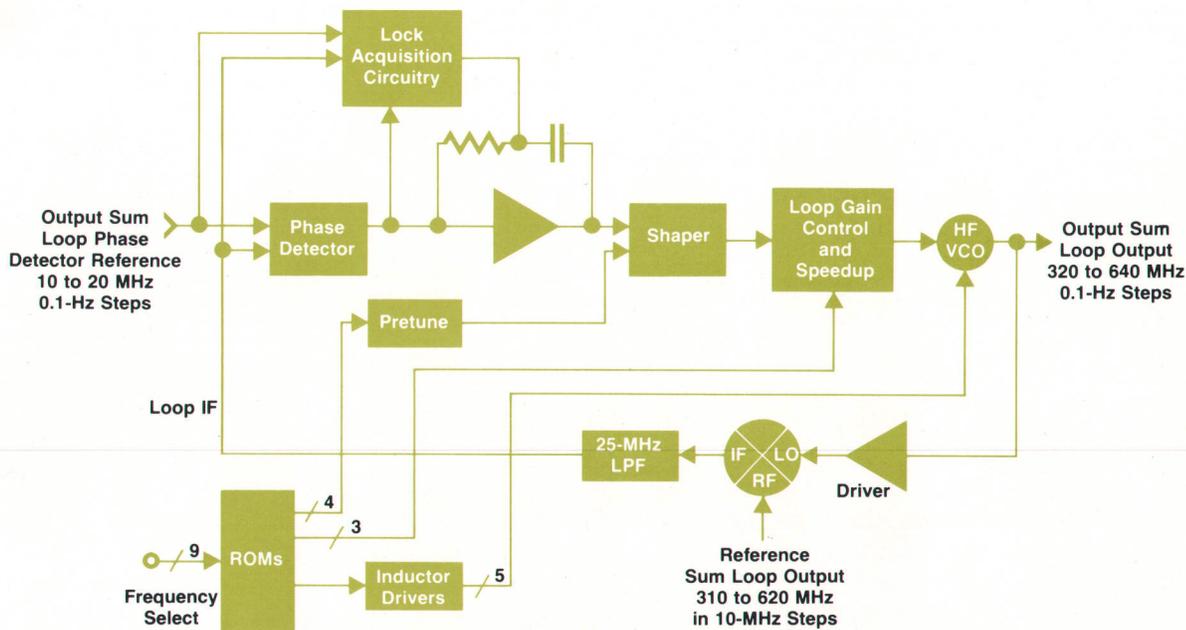


Fig. 4. Simplified block diagram of the output sum loop, high-frequency voltage-controlled oscillator (HF VCO), and ROM controller.

monolithic differential pairs connected to a common collector resistor was found to be the most effective solution at the highest frequencies. The schematic for this switch is given in Fig. 3.

Isolation in the off state is approximately 35 dB for frequencies up to 1 GHz. A switch is turned off by removing the current from a differential pair, causing the transconductance to drop to a low value.

Inexpensive PIN diodes are used for the low-frequency switches, since there is less off-state leakage due to shunt capacitance. The driving circuit is a simple TTL demultiplexer.

### Reference and Output Sum Loops

The output signal of the reference section contains unwanted sidebands, multiples of 10 MHz, as high as -40 dBc. The reference loop acts as a narrow-band tracking filter, cleaning up this spectrum with minimum degradation of its low-phase-noise quality. Summing 10 or 20 MHz also adds 10-MHz steps to the 310-to-620-MHz output signal.

The output sum loop has similar input signals. It combines the 310-to-620-MHz reference loop output with the 10-to-20-MHz signal stepping in 0.1-Hz steps. The requirements on phase noise and switching speed are identical for both loops. Therefore, it was possible to use interchangeable phase-lock circuits and oscillators for both

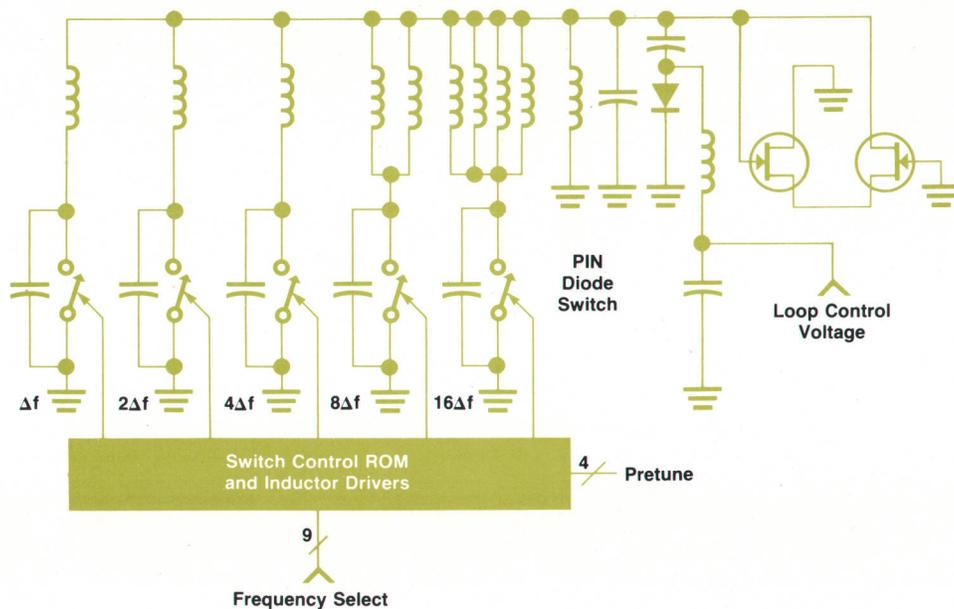


Fig. 5. The VCO in the output sum loop is this 320-to-640-MHz switched reactance oscillator. It meets requirements of low phase noise and low tuning sensitivity.

loops. Fig. 4 shows a simplified block diagram of the output sum loop including the VCO with its ROM control.

Starting with the high-frequency VCO, the output sum loop is designed with two paramount objectives. First, low phase noise of the free running oscillator is essential. In phase-locked operation the phase noise of the VCO is suppressed by the loop gain. Close to the band edge, where the loop gain approaches zero, and outside the bandwidth, VCO noise dominates. Second, low tuning sensitivity is required to minimize the effect of unavoidable noise on the tuning line of the VCO. These two objectives led to the concept of the switched reactance oscillator pictured in Fig. 5.

The resonator consists of five inductor arrays. Switched by a ROM in binary fashion, they provide 32 frequency steps. A varactor tunes between the frequency intervals to give continuous frequency coverage. Compared to a conventional VCO with a varactor covering the entire 310-to-640-MHz range, this switched scheme results in drastically reduced tuning sensitivity. It also allows operating the varactor at high bias levels where its Q is maximal.

High Q of the total resonator, a prime requirement for low phase noise, was further achieved by realizing the inductor arrays as shorted transmission lines in a low-loss stripline structure and by switching them with low-resistance PIN diodes. Q varies between 150 and 250 over the frequency range. The nature of the resonator also allows high RF signal levels ( $\pm 10V$  peak), fast switching, and precise pre-tuning. The active circuit consists of a source follower feeding a common-gate FET stage.

Single-sideband phase noise of the free running VCO in a 1-Hz bandwidth was measured as  $-120$  to  $-130$  dBc at 20 kHz offset, and  $-138$  to  $-145$  dBc at 100 kHz offset.

### Lock Acquisition

Fig. 6 shows the working of the output sum loop in more detail. The circuitry is divided into two major blocks which relate to the two operating modes of the loop, lock acquisition and locked operation. The function of achieving lock will be discussed before the locked loop circuitry.

The two phase detector references are limited in ECL

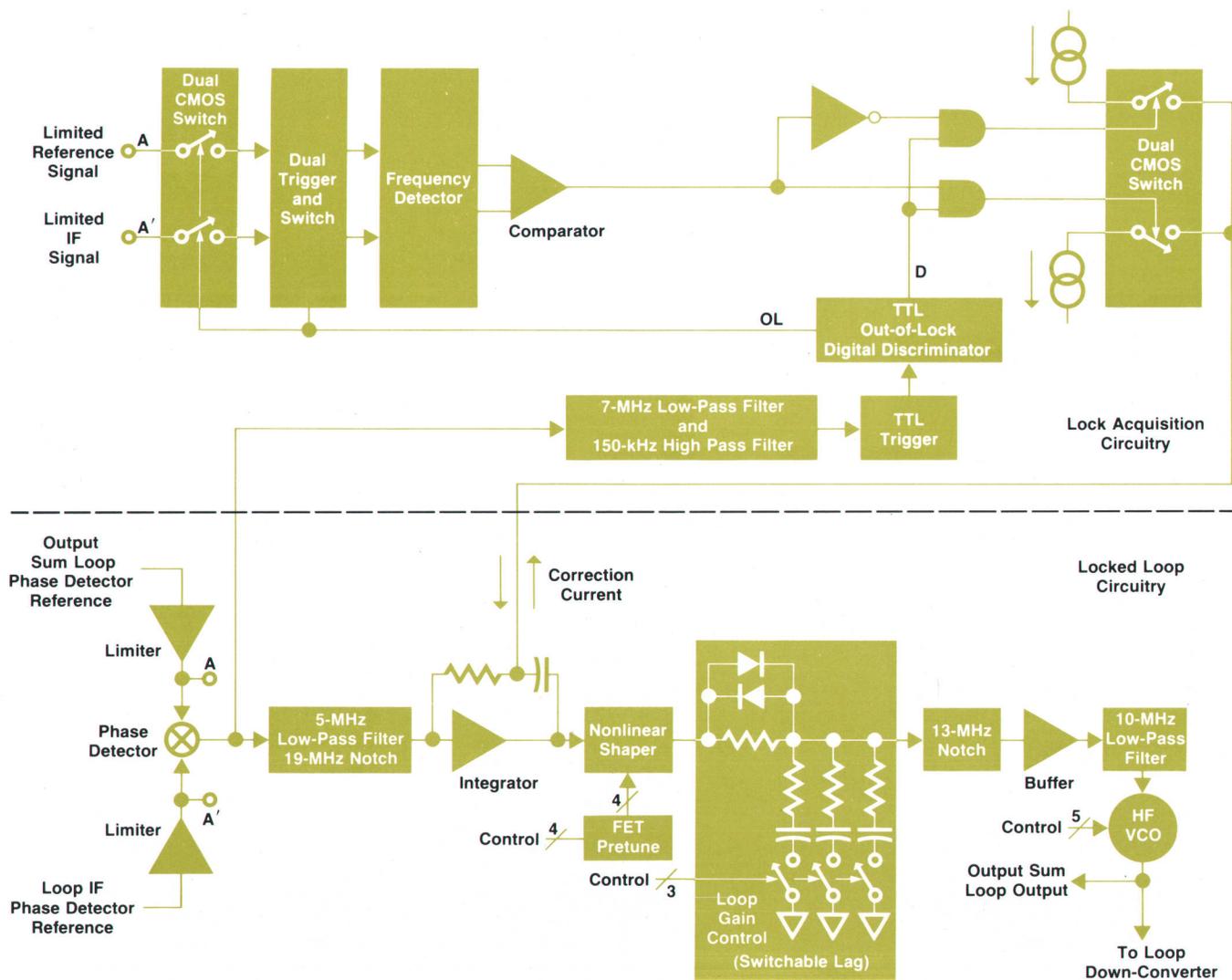


Fig. 6. Functional diagram of the output sum loop.

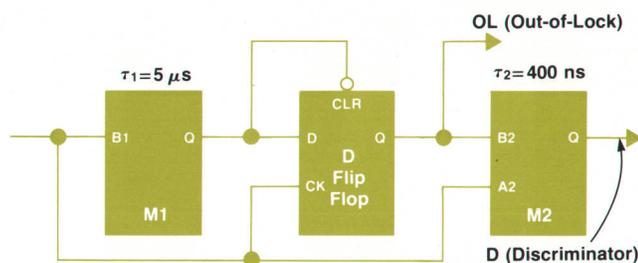
limiters to remove amplitude differences. These limiters drive a phase detector consisting of a high-level mixer; they also drive the frequency detector circuitry.

With the loop out of lock, the phase detector produces an output containing a beat note at the difference between the two input frequencies. This signal is filtered by a seven-MHz low-pass filter and an active 150-kHz high-pass filter to remove components other than the difference frequency. It is then converted to TTL levels in a high-speed comparator circuit to trigger the out-of-lock digital discriminator, diagrammed in Fig. 7.

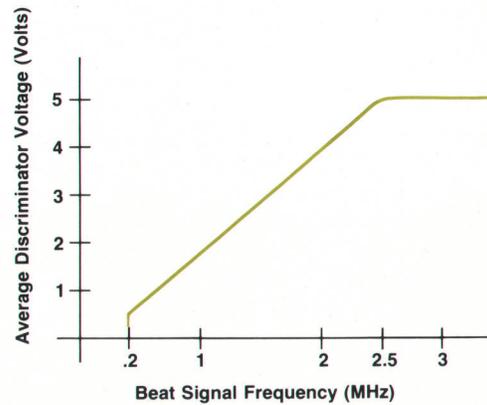
The out-of-lock digital discriminator signals are derived from the period of the beat note. Assume the D flip-flop is reset. The beat note will clock monostable M1 on a rising edge. Monostable M1 will go high one gate delay after the rising edge of the beat note. Since this signal is also timing the D flip-flop and monostable M2, they both stay in the reset state. If the next rising edge comes after a time delay of 5  $\mu$ s, M1 will have already reset and the same state will result. This case happens when the loop is within 200 kHz of lock.

If the beat note happens with a period of less than 5  $\mu$ s the D flip-flop is set and the out-of-lock signal is produced by the next rising edge of the beat note. The out-of-lock signal controls several functions, one of which is to enable monostable M2 to act as a digital discriminator, producing a pulse of 400-ns width at the rate of the beat signal. At a rate of 2.5 MHz (400-ns period) and higher, M2 will be on all the time. Below 2.5 MHz the duty cycle of the pulse signal out of M2 will decrease proportionally with the period of the beat signal. The average output voltage of the digital discriminator is diagrammed in Fig. 8. This discriminator signal provides the magnitude of the feedback to steer the loop into lock.

By digitally AND-gating the out-of-lock and discriminator signals, a signal is produced to control a current source and sink that rapidly charges or discharges the integrator capacitor to steer the loop into lock. With the loop more than 2.5 MHz from lock the correction current is fully on. The magnitude of the correction current decreases proportionally as the loop approaches lock. With the loop closer than 200 kHz, the out-of-lock signal disappears and the entire block of lock acquisition circuitry is switched off. The phase-locked loop now rapidly completes lock acquisition, since the beat note is well within its capture range. With the proportional feedback from the digital dis-



**Fig. 7.** The out-of-lock digital discriminator generates the out-of-lock signal (OL) that controls several functions in the output sum loop. It also produces a signal (D) that represents the difference between the loop input and output frequencies.



**Fig. 8.** Average value of the digital discriminator's D output is a function of the beat or difference frequency between the input and output of the output sum loop. This signal provides the magnitude of the feedback to steer the loop into lock.

criminator the loop is able to acquire lock very rapidly for any size frequency step. Total lock acquisition time is less than 75  $\mu$ s.

### Locked Operation

Below the dotted line in Fig. 6 is the circuitry that is active in locked operation. The phase detector output is low-pass filtered and sent to the integrator. The output of the integrator is summed with the pretune voltage in a nonlinear shaper to compensate for the varactor tuning curve of the VCO. This signal is sent through the loop gain adjust circuit, which compensates for oscillator gain changes caused by inductor changes when switching oscillator bands. The signal is then low-pass filtered again and buffered to drive the VCO tune line.

With a locked loop there is no beat note from the phase detector and the entire lock acquisition circuitry is put in a static mode to eliminate spurious signals from this source. The low-pass filtering of the phase detector signal is accomplished in three distinct filters. This allows an optimum balance between bandwidth and rejection to get maximum suppression of spurious reference sidebands. All spurious responses in the loop are below -100 dBc.

The action of the pretune circuit, nonlinear shaper, and loop gain adjust circuit allows precise control of the oscillator. A loop bandwidth of 250 to 500 kHz can be maintained. To take advantage of this high loop bandwidth to suppress close-in oscillator noise, each of the circuits in the loop gain path had to be designed for low noise. An example is the discrete integrating amplifier, which has two low-noise transistors in its front end. Also, because of the variation in VCO tuning sensitivity when switching inductor bands, the loop gain adjust circuitry serves a dual role. It attenuates pretune circuit and shaper noise as well as controlling loop gain. The pretune circuit switches are designed with low-noise JFETs and the shaper is designed for low noise.

The result of these design considerations is an extremely low phase-noise floor in the locked system. Excluding reference phase noise, the phase-locked loop achieves a noise floor of -140 to -143 dBc as close as 1 kHz to the carrier.

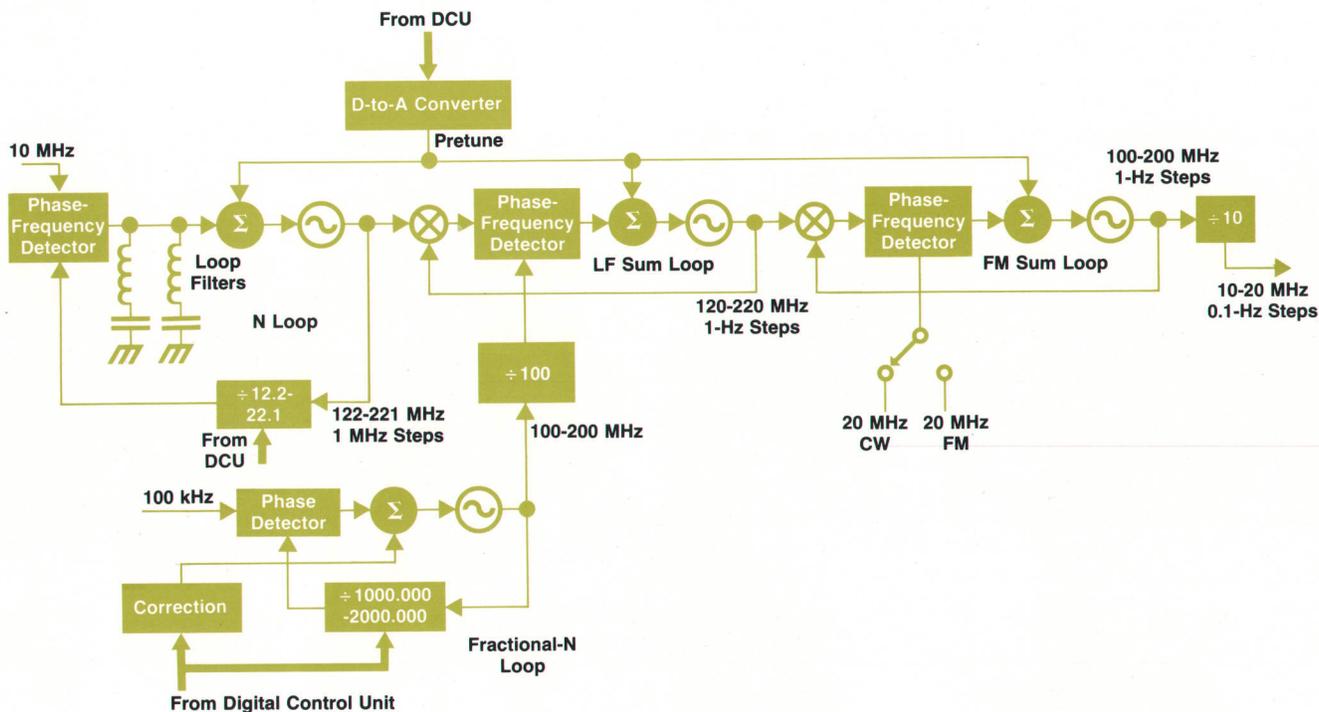


Fig. 9. 8662A low-frequency section has four phase-locked loops and produces a signal from 10 to 20 MHz in 0.1-Hz steps.

### Low-Frequency Section

The fine frequency steps of the 8662A are synthesized in a multiple loop system that produces a signal covering 10 to 20 MHz in 0.1-Hz steps. Fig. 9 is the block diagram of the low-frequency section.

The 10-to-20-MHz signal is summed directly into the output sum loop, so the spectral purity and frequency switching time requirements are the same as those of the 320-to-640-MHz sum loop output. A well known tradeoff in synthesizer design is between frequency resolution on the one hand and spectral purity and frequency switching time on the other. For indirect, or phase-locked loop synthesizers, this tradeoff occurs because the need to filter spurious sidebands that are offset from the carrier by the frequency resolution limits the maximum loop bandwidth. The maximum loop bandwidth then limits the loop gain available to reduce oscillator noise sidebands. The frequency switching speed is also determined by the loop bandwidth. In the 8662A, a significant improvement to this tradeoff is achieved by using a fractional-N loop with correction circuits that effectively cancel the spurious sidebands, rather than filtering them with a phase-locked loop. By setting a loop bandwidth that exceeds the minimum frequency resolution and employing digital-to-analog converters to cancel spurious signals at the phase detector, high resolution and good spectral purity are achieved simultaneously.

At present, fractional-N loop technology is capable of good spectral purity and switching speed. However, to exceed the signal quality of the output sum and reference loops and reference section, the output of the fractional-N loop must be divided down to 100 to 200 kHz, referred to the output. As a signal's frequency is divided, phase noise modulation is reduced by the divide number. As a result, a

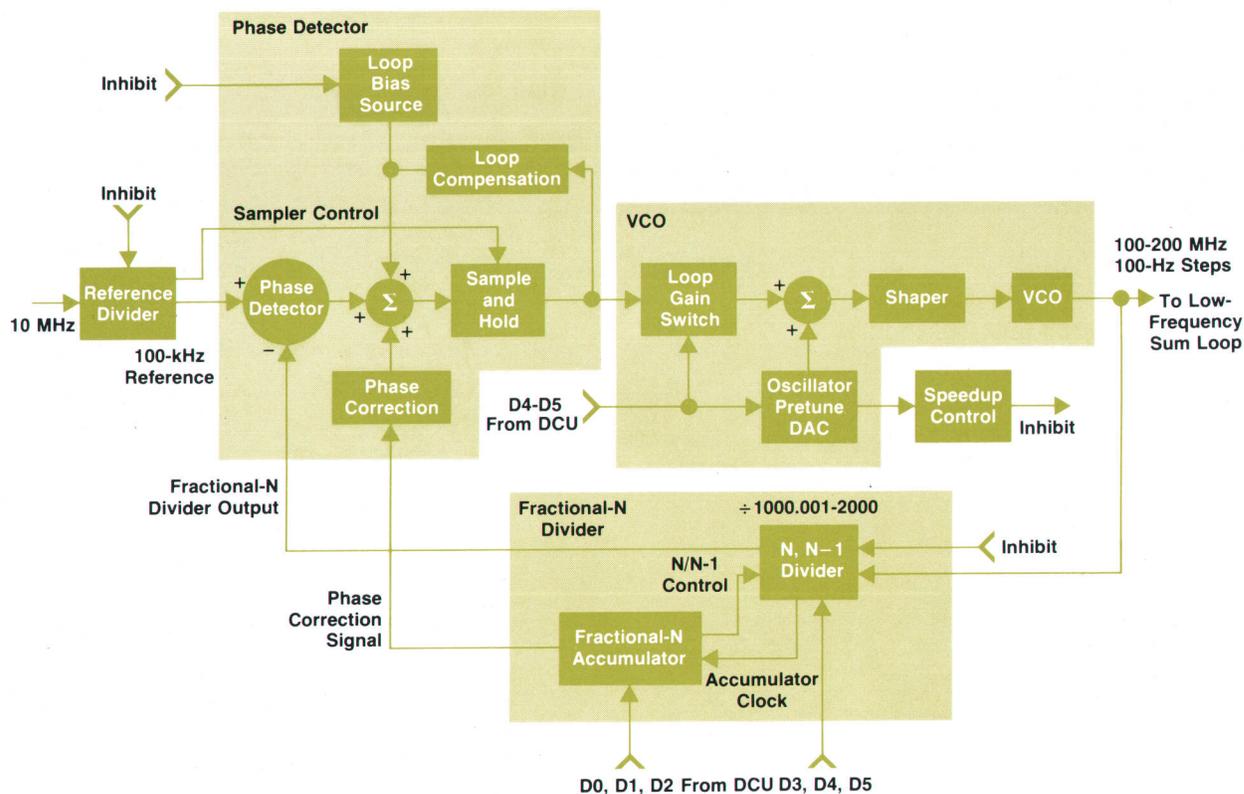
100-to-200-MHz fractional-N loop signal after division by 1000 exhibits excellent spectral purity.

Since the output sum loop requires 10 to 20 MHz and the fractional-N loop provides only 100 to 200 kHz, a system of two phase-locked loops is used to synthesize the increased frequency range. This synthesis is accomplished with a first loop that generates 122 to 221 MHz in 1-MHz steps and a second loop that sums the fractional-N loop, after division by 100, with the first loop. The result is a frequency covering 120 to 220 MHz in 1-Hz steps. A third phase-locked loop subtracts a 20-MHz signal that can have frequency modulation. The output of this loop is then 100 to 200 MHz in 1-Hz steps with frequency modulation capability. This 100-to-200-MHz signal is divided by ten, providing 10 to 20 MHz in 0.1-Hz steps, with FM capability and excellent spectral purity. By generating a signal at 100 to 200 MHz and then dividing it by ten, a high loop bandwidth can be maintained for these loops. Compared to a set of loops operating at 10 to 20 MHz, the frequency switching time of the higher-frequency loops is reduced by a factor of ten because phase or frequency settling time is inversely proportional to loop bandwidth.

### Fractional-N Loop

The fractional-N loop of the 8662A provides the lower six decades of frequency resolution. The fractional-N technique<sup>1,2</sup> is able to meet noise and switching speed performance requirements that would otherwise require three phase-locked loops. The output of the fractional-N loop has a frequency of 100.0001 MHz to 200 MHz in 100-Hz steps. This is divided by 1000, giving 0.1 Hz steps at the output of the 8662A.

The loop has a bandwidth of approximately 9 kHz.



**Fig. 10.** Fractional-N loop provides the lower six decades of frequency resolution. Its output has a frequency of 100.0001 to 200 MHz in 100-Hz steps. This is divided by 1000 to give 0.1-Hz steps at the 8662A output.

Worst-case switching transient time to within 1 MHz (1 kHz at the 8662A output) of the final frequency is 250  $\mu$ s. Settling occurs at a rate of about one decade reduction in offset per 150  $\mu$ s. The single-sideband phase noise of the fractional-N loop is more than 10 dB below the instrument's noise at its output, making the noise contribution of the fractional-N loop less than 1 dB.

Although the fractional-N loop block diagram, Fig. 10, is similar to conventional divide-by-N phase-locked loops, there are many differences. The output frequency ( $f_o$ ) of a phase-locked loop is N times the reference frequency ( $f_r$ ). The fractional-N divider allows  $f_o$  to have a step size less than  $f_r$ . A fractional-N divider is an integer frequency divider whose divide number (N) can be altered by one (N, N+1 or N,N-1) at a desired duty cycle (D). This makes the average divide number (M) for an N,N-1 divider a non-integer.

$$D = \frac{\text{(Number of VCO cycles counted with N-1 per base period)}}{\text{(Total number of VCO cycles counted per base period)}}$$

$$M = N - D$$

The average output frequency is M times  $f_r$ . The output also has spurs because the instantaneous frequency varies. These spurs are caused by the phase shifting of the divider output by changing N. The phase shifting results in ripple on the output of the phase detector. The ripple can be reduced by filtering, but this approach requires that the loop bandwidth be less than the minimum step size. To

maintain fast switching in the 8662A, the ripple is reduced by the following method, which does not require a narrow loop bandwidth.

The time and amount of phase shift is determined by the accumulator that generates the divider modulus control signal at the desired duty cycle. The deviation of the fractional-N divider output phase from a reference 100 kHz that is due to the fractional-N process is known and is corrected for. A correction circuit generates a signal that is equal and opposite to this deviation. This is added to the output of the phase detector. The resultant signal is sampled once per reference period and is used to control the voltage-controlled oscillator (VCO). This VCO control signal contains feedback information that removes the spurious ripple.

Fast switching speed is an important performance characteristic of the 8662A. The fractional-N loop has specific circuitry to address this need. Three major speed-up circuit functions are performed: pretuning the VCO control voltage, phase detector transient reduction, and loop gain (bandwidth) control.

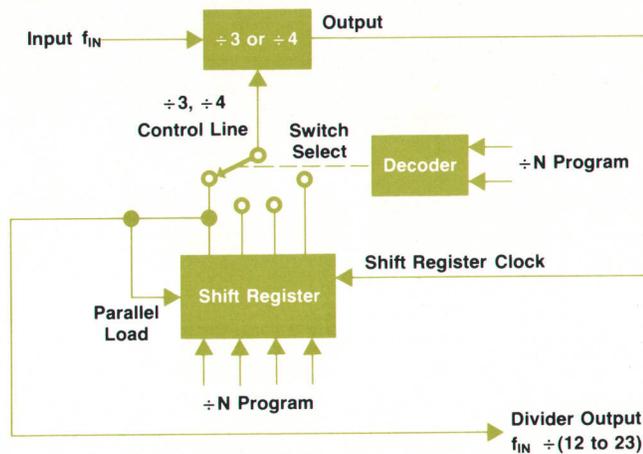
A voltage-dependent variable-gain amplifier is used to linearize the VCO tuning characteristic. The VCO is set in 4-MHz increments (4-kHz at 8662A output) by the digital control unit by means of a digital-to-analog converter (DAC). The DAC output is filtered for noise reduction. When a DAC output change is detected the filter output is speeded up by turning on a FET that is in shunt with the series resistor of the filter.

To minimize the transient applied to the phase detector filter (loop compensation) the phase detector is disabled, the current summing amplifier offset bias is removed, and the reference divider and fractional-N divider are halted in a reset state. This is done while the pretune transient is settling time, the fractional-N loop is returned to normal operation. The reference and fractional-N dividers are started in phase. This insures that the first output of the phase detector compares full reference and fractional-N counter periods. This output then reflects the necessary correction needed to lock the loop.

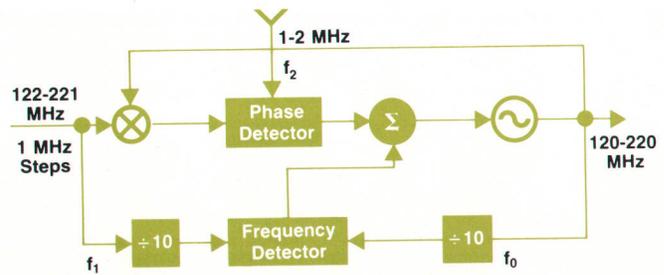
For fractional-N loop output frequencies 160 MHz and higher, an attenuator in the phase detector is switched out. This increases the loop gain and partially compensates for the loop gain reduction that results from an increasing divide number. The loop settling time is reduced as the loop gain is increased.

### 122-to-221-MHz Loop (N Loop)

The phase-locked loop that synthesizes 122 to 221 MHz in 1-MHz steps with good spectral purity presented a number of design challenges. The conventional approach for such a loop is to lock a voltage-controlled oscillator to a 1-MHz reference. A programmable divider that covers 122 to 221 would then be required. Within the bandwidth of the phase-locked loop, the output phase would follow the reference phase, multiplied by 221. This represents a degradation of reference phase noise sidebands of about 47 dB. Even with the lowest-phase-noise dividers and phase detectors available, excellent spectral purity cannot be achieved with such a high divide number. The solution to this problem was to use a fractional-N divider that has divide numbers of 12.2 to 22.1 in steps of 0.1. The reference frequency is changed to 10 MHz and the output frequency steps are 0.1 times 10 MHz or 1 MHz. A phase noise enhancement of only 22.1 or 27 dB preserves excellent output spectral purity. The spurious signals at multiples of 1 MHz are reduced by placing a series of notch filters in the loop between the phase detector and the VCO control voltage.



**Fig. 11.** This 12-to-23 integer divider is used in the phase-locked loop that generates 122 to 221 MHz in 1-MHz steps. A separate circuit controls a fractional digit to give divide numbers of 12.2 to 22.1.



**Fig. 12.** The low-frequency sum loop combines the output of the 122-to-221-MHz loop with the output of the fractional-N loop which, after division by 100, has a frequency of 1 to 2 MHz.

The programmable divider in this loop is made up of a 12-to-23 integer divider and a separate circuit that controls a fractional digit, so that a total divide number of 12.2 to 22.1 is obtained. This 12-to-23 integer divider presented a substantial design challenge. Not only are MSI ECL counters unable to operate at such a high frequency, but ECL  $\div 10/11$  prescalers do not allow divide numbers of 12 to 23. A variable-ratio prescale divider was developed using SSI and MSI ECL devices (Fig. 11).

The design is split into two parts, a variable-ratio prescaler and a control for the modulus of the prescaler. Since the lowest overall divide number is 12, and a relatively simple prescaler was desired, division by 3 or 4 was selected. For example, to divide by 13, the prescaler is programmed to divide the input by 3 for three cycles of the output of the prescaler and by 4 for one cycle of the output of the prescaler. A total of  $3 \times 3 + 4 \times 1$  or 13 pulses are input for every output pulse, and a division by 13 results. The control circuit that selects the modulus of the divider is critical because of the short time available to change the modulus, about 10 nanoseconds. The control circuit uses a shift register as a ring counter. The last flip-flop in the shift register is used to detect a terminal state and load the shift register from its parallel data inputs. One of the outputs of the shift register is connected to the modulus of the 3-or-4 divider by a selector. The output of the selector is a signal with programmable duty cycle and pulse length that controls the number of divide-by-three or divide-by-four cycles.

### Sum Loop

To combine the output of the 122-to-221-MHz loop, also called the N loop, with the 1-to-2-MHz fractional-N signal, a sum loop is employed (Fig. 12). The oscillator output signal is mixed with the N loop output to an IF equal to the frequency of the fractional-N loop VCO divided by 100. During frequency switching the IF can be well outside the loop bandwidth, leaving the loop unable to lock. Two solutions to this problem are required. One is a frequency detector that drives the VCO towards the desired frequency for initial offsets of about 1 MHz. The second part of the phase lock problem is more subtle and difficult to deal with. When the sum loop VCO is properly locked, it is always lower in frequency than the N loop VCO. However, if during frequency switching the sum loop VCO is driven above the sum of the N loop frequency and the phase detector input frequency, the frequency detector operation inverts and

# A Switching Power Supply for a Low-Noise Signal Generator

by Gerald L. Ainsworth

The use of switching regulated power supplies in signal generators has not been the usual practice, perhaps because these supplies are relatively new, but more likely because of the line-related and switching ripple voltages present in these supplies. Certainly one does not want switching transients in a low-noise signal generator like the 8662A. However, in an instrument made up of more than 5000 components, with the reliability of each component decreasing exponentially with increasing temperature, there is powerful incentive to minimize the operating temperature. The efficiency of the switching supply minimizes the heat it generates, causing its own components to remain cool and helping keep the other components cool as well. Other benefits of this type of supply are compactness, the ability to operate over a wide range of input voltages and frequencies, and the ability to supply the substantial power requirements of the 8662A while the power supply components are loafing in a derated environment.

## 8662A Supply Characteristics

In the 8662A's switching regulated supply, switching transients are minimized by using very high-quality filter components, keeping switching current loops tight, and minimizing areas with large voltage rates of change. To minimize line-related spurs, we use an extremely high-gain "slow loop" that suppresses multiples of 60 Hz out to a frequency of about 2 kHz. Line-related ripple components are all less than 100  $\mu\text{V}$  rms, and switching ripple is less than 300  $\mu\text{V}$  rms (10 dB lower on the linear switching-preregulated outputs).

All outputs are limited in voltage and current to protect both the synthesizer and the supply. The line inputs are protected against high and low voltages. A high-temperature shutdown system is included.

For good EMI (electromagnetic interference) performance, the high-power switching components are isolated from the case.

## Torture Tests

One of the prototypes, affectionately known as "Bismarck," operated eight days at 80°C and three days at -20°C in an environmental chamber. These tests terminated when the chamber—not the supply—failed. Five pilot-production units operated at 30% overload for nine months, 24 hours per day. They were subjected to high line and low line voltages with shorts and opens applied regularly at the outputs. The temperature varied between 25°C and 55°C.

## Acknowledgments

I would like to thank Marilyn Lawrence, who helped build, test, and stress the supply.

## Gerald L. Ainsworth



Jerry Ainsworth has been with HP for 14 years. He has designed a variety of circuits and served as project leader, project manager, and section manager at various times. He's a member of the IEEE and is named inventor on three U.S. patents. He designed the power supply for the 8662A Signal Generator. Jerry graduated from Stanford University in 1956 with a BSEE degree. He served in the U.S. Navy until 1958, then returned to Stanford and received his MSEE degree in 1961. A native of Omaha, Nebraska, he has three children and lives in Palo Alto, California. Among his interests are tennis, classical music, and "wood-butcherin'g."

drives the sum loop VCO to a frequency determined by a latched amplifier. To prevent this condition, the N loop VCO and sum loop VCO frequencies are divided by 10 and compared in a frequency detector. If the sum loop VCO is above the N loop VCO, it is driven by the frequency detector to the lower side of the N loop VCO where it can lock properly. Accurately tuned VCOs are therefore not required and there is no degradation of frequency switching speed. To improve frequency switching speed the oscillators in the loops are tuned by digital-to-analog converters to frequencies close to their desired lock frequencies (pretuning). To reduce the sensitivity of the VCO tuning voltage to noise from this source, an attenuator, Fig. 13, is placed in series with the tuning voltage line. To reduce the time required to charge the 0.33- $\mu\text{F}$  capacitor, a switch bypasses the normal path to the VCO and then opens before acquisition begins.

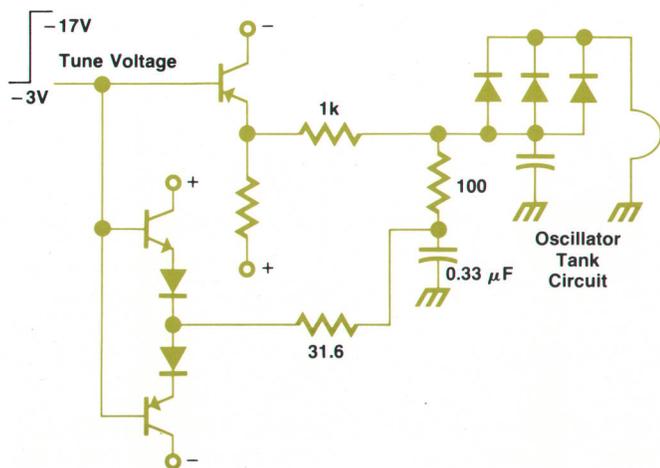
## Frequency Modulation

Frequency modulation is translated to the carrier in the 8662A by means of a wide-bandwidth phase-locked loop. A 20-MHz signal with the desired FM is subtracted from the

120-to-220-MHz sum loop output in a 2-MHz-bandwidth loop. The FM signal at the 20-MHz reference to this FM sum loop has equivalent peak phase modulation of 10 radians at a 100-kHz rate, corresponding to an FM deviation of  $\pm 1$  MHz. The mixer used as a phase detector in this loop is capable of handling about  $\pm 1$  radian of phase modulation at its input. By having adequate loop gain at 100 kHz (greater than 10), feedback reduces the 10-radian input phase modulation to less than 1 radian of phase difference between the phase detector inputs. All of these phase differences are peak deviations at a 100-kHz rate.

## Spurious Evaluation and Optimization

A major 8662A design task was the elimination of spurious signals on the output of the signal generator. With eight oscillators and seven phase-locked loops, it was immediately realized that troubleshooting spurious problems would be a tedious process. Several innovative approaches were taken that simplified the task. First, as an aid to rapid troubleshooting and servicing, all important RF signals and interconnects are available on coaxial cable lines between

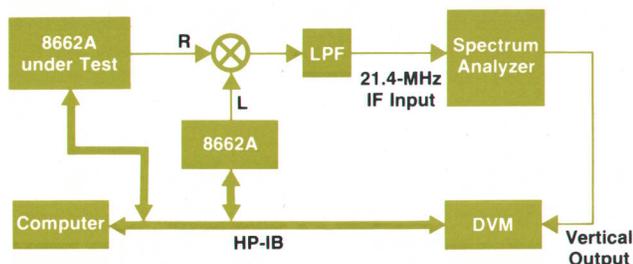


**Fig. 13.** An ac attenuator in the tuning voltage lines of the low-frequency section oscillators reduces sensitivity to noise from the digital-to-analog converters used for pretuning.

RF modules. The inspection of signals and replacement of entire modules is rapid and straightforward. Second, the generation of spurious signals was treated on the instrument level as a myriad of internal communication paths. Basically, almost all spurs result from the unwanted coupling of a signal from one area to another. For example, a VCO signal can couple into a phase detector, which senses an equivalent phase modulation that possibly cannot be filtered. A matrix of possible couplings was constructed assuming that VCOs and reference frequencies represent spur transmitters, and VCOs and phase detectors are spur receivers. Once the system of phase-locked loops was assembled, each of the elements of the matrix was analyzed for potential spur coupling and measured level of coupling. Based on the results of this study, isolation, filtering and required shielding were determined.

In addition to these coupling mechanisms for spur generation, some other potential problems are signal harmonics, mixer intermodulation spurs, and the conversion of spurs at one offset from the carrier to another by sampling mechanisms. Each of these areas required careful design attention.

A third significant development in the troubleshooting of spurs was a high-dynamic-range programmable spectrum analyzer system, assembled from a 21.4-MHz spectrum analyzer IF and an 8662A as a swept local oscillator. Spur



**Fig. 14.** System to measure the spurious output of the 8662A uses a 21.4-MHz spectrum analyzer IF section and a second 8662A as a swept local oscillator. The second 8662A improves the analyzer's phase noise.

measurements to  $-105$  dB at greater than 40 kHz from the carrier can be made rapidly on this system.

Fig. 14 is a diagram of the spurious signal measurement system. Previous solutions to this problem involved the use of narrow-bandwidth (less than 10 Hz) receivers, carefully tuned to the spur frequencies. Narrow bandwidths were required to be able to measure spurs below the phase noise

#### Fred H. Ives



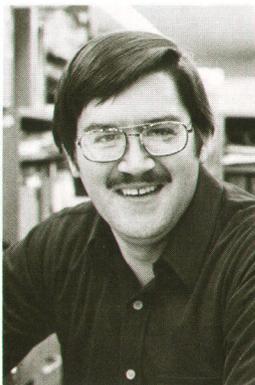
Fred Ives received his BSEE degree in 1972 from Massachusetts Institute of Technology. Joining HP in July of 1972, he designed the reference sum loop and the output sum loop for the 8662A Signal Generator. He's now involved with high-speed IC design. A resident of Cupertino, California, Fred enjoys restoring his 1970 Jaguar XKE and remodeling older homes. He is to be married this coming spring, and next summer will transfer to HP's division in Spokane, Washington, where he's building a new hillside home.

#### Dieter Scherer

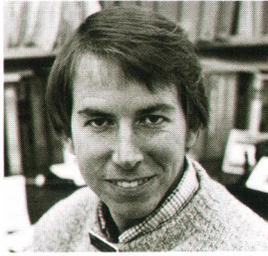


Dieter Scherer was born in Bad Reichenhall, Bavaria and received his Diplom Ingenieur from the Technical University of Munich in 1967. After half a year with a German firm, he joined HP's Microwave Division in Palo Alto. He acquired his MSEE degree from Stanford University in 1972. Dieter has designed thin-film microcircuits for the 8660C/86602A Signal Generator and the HF VCO for the 8662A Signal Generator. He had overall responsibility for the 8662A HF section design. A senior member of IEEE, he's the author of a paper on low-phase-noise microwave sources. Dieter is married, has two sons, and lives in Palo Alto, California. His interests include photography, cabinet making, camping, and coaching youth soccer.

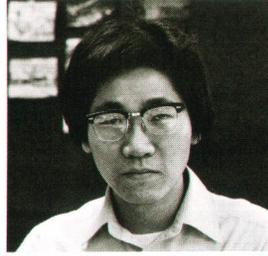
#### Donald W. Mathiesen



Don Mathiesen was born in Renton, Washington and attended the University of Washington at Seattle, receiving his BSEE and MSEE degrees in 1971 and 1972. With HP since 1972, he's done noise investigation and microprocessor development system support, and he designed the fractional-N loop and other circuits for the 8662A Signal Generator. Currently project manager for an RF test system, he's a member of the IEEE and the IEEE Computer Society. Don is married, lives in Cupertino, California, and has a one-year-old son who heads his list of interests. The rest of the list includes horseback riding, skiing, the securities market, personal computing, fishing, sailing, and scuba diving.

**William J. Crilly, Jr.**

Skip Crilly designed the N, LF sum, and FM sum loops, and was also responsible for spurious signal evaluation and optimization in the 8662A Signal Generator. He received his BSEE degree in 1973 from Case Western Reserve University. Born in Chicago, Illinois, Skip lives in Spokane, Washington and enjoys skiing, backpacking, amateur astronomy and amateur radio.

**Bill S. Chan**

Bill Chan attended the University of Washington at Seattle, received his BSEE degree in 1970 and his MSEE degree in 1972, and joined HP in 1973. He designed the reference section of the 8662A Signal Generator. Born in Portland, Oregon, Bill lives in Los Altos, California. He's a member of the IEEE, a photographer, and an amateur radio operator for the past 15 years.

of the unit under test and the spectrum analyzer's local oscillators. Since the 8662A has an extremely low sideband noise level, it became possible to use wider bandwidths up to 1 kHz.

The second 8662A is used as an LO to improve the spectrum analyzer's LO phase noise. Spurious signals on the LO generally are suppressed if the offset of the spur changes as the LO is swept. This is because the spur itself is swept in frequency through the 21.4-MHz filter faster than the IF is designed to respond. It is therefore reduced in level before being detected. By stepping the frequency of the 8662A under test many spur mechanisms can be quickly measured without tedious calculations to uncover their exact offset frequencies. A high level of measurement confidence is thus obtained for this important specification.

**Acknowledgments**

In addition to those acknowledged in Rolly Hassun's article, the following colleagues have contributed significantly to the development of the HP 8662A: Cory Boyan did the original design of the FM driver and FM oscillator circuit, achieving a low-phase-noise FM source. Paul Zander and John Hasen completed the FM circuit design and in particular perfected FM linearity and accuracy.

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# A High-Purity Signal Generator Output Section

by David L. Platt and Donald T. Borowski

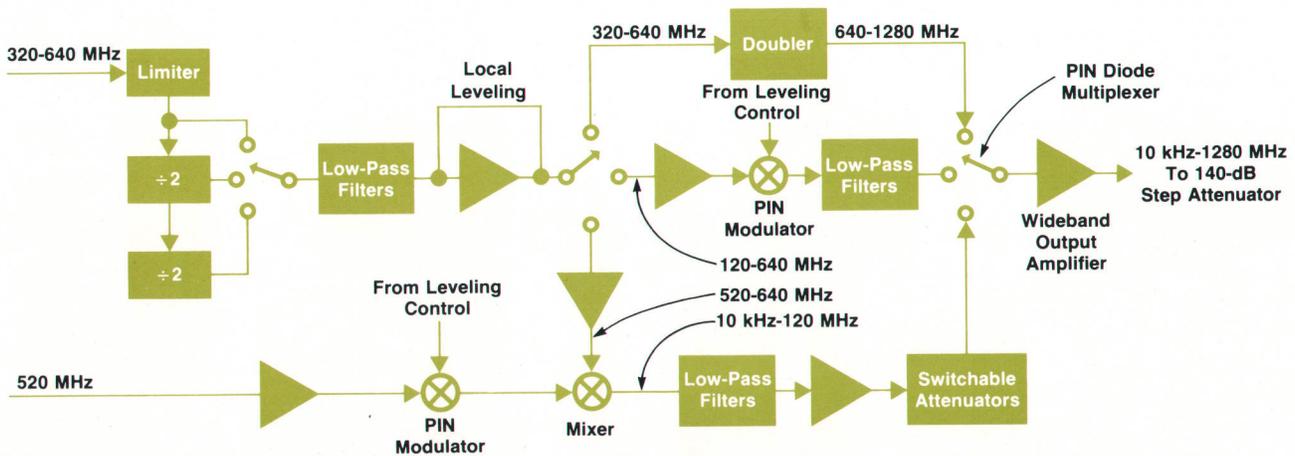
**T**HE TASK OF CONVERTING the 320-to-640-MHz range of frequencies synthesized by the 8662A Synthesized Signal Generator's phase-locked loops to the full range of 10 kHz to 1280 MHz is the function of the output section. Amplitude modulation capability and leveling are also provided by this section. The frequency conversion is done by forming three separate bands: 10 kHz to 120 MHz, 120 to 640 MHz, and 640 to 1280 MHz (see Fig. 1). All three bands converge at the input of the final wideband output amplifier. Each band has a separate level modulator and separate signal handling circuits to maintain a high signal-to-noise ratio and freedom from spurious signals.

Special design consideration was given to the reduction of AM noise introduced by the output section. If the AM noise is not sufficiently below the phase noise floor of the instrument, it will increase the broadband noise floor and degrade the sensitivity of adjacent-channel tests on receiv-

ers. Furthermore, AM noise can be converted to phase noise by a variety of mechanisms.

AM noise can be classified into two categories: multiplicative and additive. The multiplicative component results from AM modulation of the carrier by the leveling loop. The sources of this modulation can be the drive circuits or the internally generated noise of the modulator control diodes. The additive component occurs if the level of the carrier is allowed to drop too close to the thermal noise floor.

Throughout the design of the output section, a Schottky barrier peak detector using a low-impedance video load was used to monitor the level of the AM noise on various signal paths. The low-impedance loading on the detector minimized the noise contribution of the detector diode, allowing AM noise measurements to  $-158$  dBm/Hz. A typical AM noise measurement system is shown in Fig. 2. The system is calibrated by summing the outputs of two sources,



**Fig. 1.** 8662A output section converts the 320-to-640-MHz signal from the phase-locked loops to the full range of 10 kHz to 1280 MHz. It does this by forming three bands of frequencies that converge at the input of the wideband output amplifier.

with one output 60 dB below the other. This simulates a single source with AM sidebands at  $-66$  dBc.

### Output Section Operation

As shown in Fig. 1, the signal from the high-frequency phase-locked loops is passed through two ECL limiters to minimize power fluctuations. Following the limiters the signal can be selectively applied to two ECL dividers to obtain frequencies between 80 and 640 MHz. Since the dividers also divide the FM deviation previously introduced, only frequencies down to 120 MHz are used. The heterodyne band produces frequencies below 120 MHz.

Because the dividers produce approximately square-wave output signals, low-pass filtering is used to remove harmonics. Because of the lack of flatness of the dividers and filters, there is a local leveling loop to flatten the output. This is important because power fluctuations would cause loop gain variations in the leveling loop that follows.

The 120-to-640-MHz signal is amplified to  $+12$  dBm before application to the AM and leveling modulator. This prevents the output signal of the modulator from being degraded by the broadband noise floor when the instrument is in its low-power vernier setting.

The level modulator uses PIN diodes because of their low

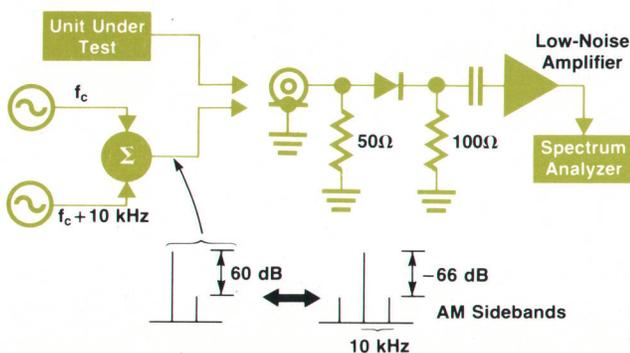
parasitics. These low parasitics allow the 40-dB dynamic range needed for 95% AM and power leveling from 5.1 dBm to 16 dBm. The low parasitics also reduce AM-to-PM conversion. However, there is one main disadvantage to PIN diodes and this is their high sensitivity. When the AM modulator is very sensitive, thermal noise sources can cause incidental modulation. Noise sources can include the modulator drive circuits and shot noise generation in the diode junctions. The 8662A's AM bandwidth is controlled by an integrator immediately preceding the modulator's input. This stage rolls off any noise contributions of the drive circuits. Also, the modulator's low-frequency circuit shunts some of its shot noise current away from its junction. Since PIN modulators produce RF harmonic distortion, a switchable low-pass filter follows the modulator.

### The Heterodyne Band

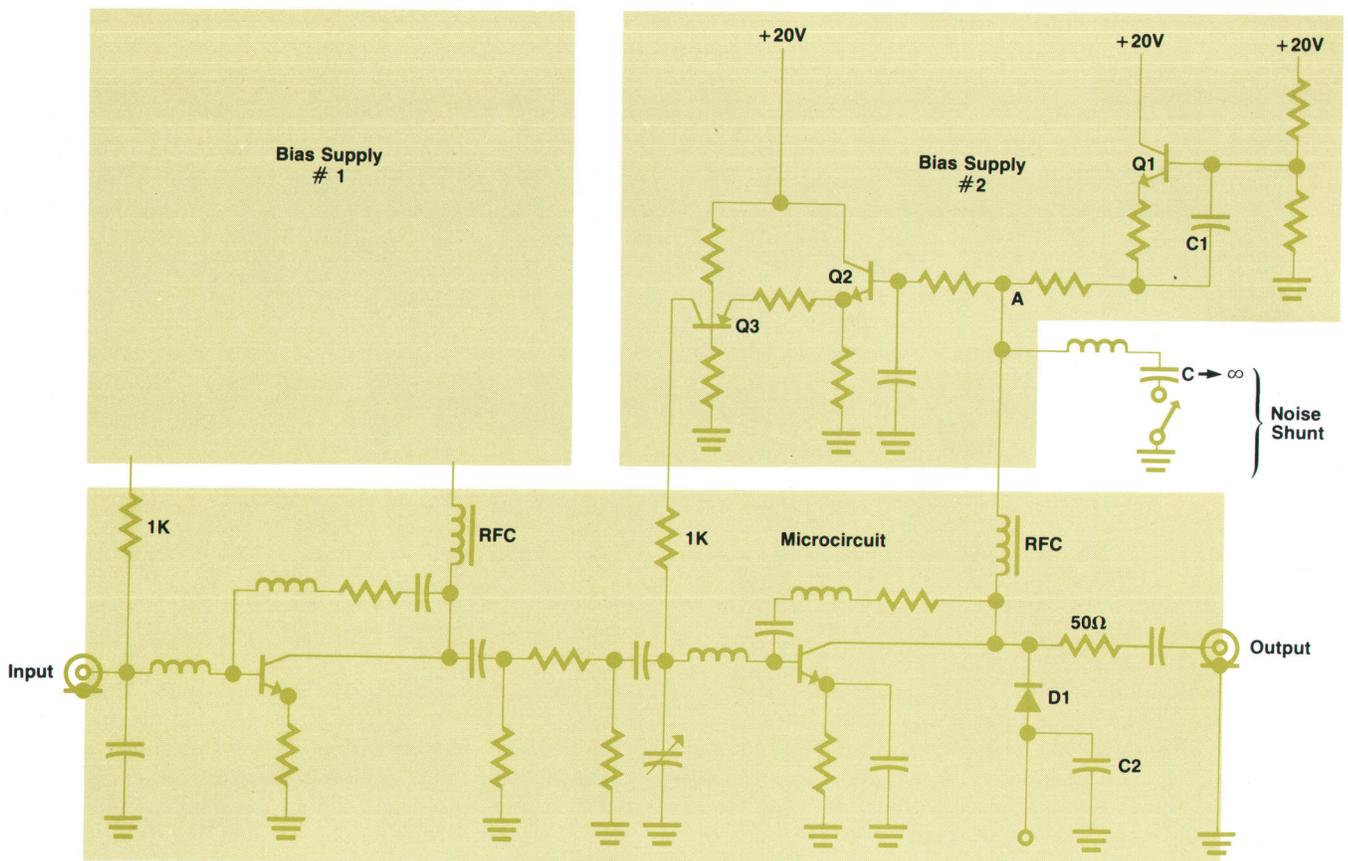
The heterodyne range of 10 kHz to 120 MHz is developed by mixing a 520-to-640-MHz portion of the local leveling loop's output with a fixed 520-MHz signal from the reference section. Extreme care was taken to adjust signal levels going to the double balanced mixer to keep the in-band spurious mixing products from becoming objectionably large. The principal spurious is the  $5 \times 4$  mixing product which crosses the carrier at 104 MHz output.

The local oscillator (LO) signal is harmonic filtered, padded to improve the LO match, and applied to the mixer at 17 dBm. In general, the lower the RF level going to the mixer, the lower the spurious level with respect to the desired output. However, too low an input level will cause the output signal to be degraded by noise.

In the 8662A the level modulator that gives vernier power control and AM capability is placed ahead of the mixer in the RF line since this input is at a single frequency (520 MHz). If the RF level to the mixer had been varied to obtain the vernier range of 10.9 dB, the output signal-to-noise ratio would have become unacceptable. Instead, a switchable set of attenuators preceded by a low-noise amplifier is placed after the mixer. When a change of power levels is programmed, these attenuators change, and the modulator-mixer level changes very little. This keeps the output level of the mixer at  $-16$  dBm  $\pm 1$  dB with no modulation



**Fig. 2.** Schottky barrier peak detector with a low-impedance video load was used during the design phase to measure AM noise down to  $-158$  dBm/Hz.



**Fig. 3.** 8662A output amplifier is a two-stage feedback amplifier realized as a thin-film microcircuit on a sapphire substrate. It provides 17 dB gain from 10 kHz to 1280 MHz.

applied. Since the switchable attenuators are inside the leveling loop, the loop gain and therefore the AM bandwidth are affected by them. This effect is compensated by a gain switching circuit in the dc control portion of the loop.

The low-pass filter following the mixer is designed to terminate IF sum products (1040-1160 MHz) instead of reflecting them back into the mixer. This further reduces spurious generation.

### The Output Amplifiers

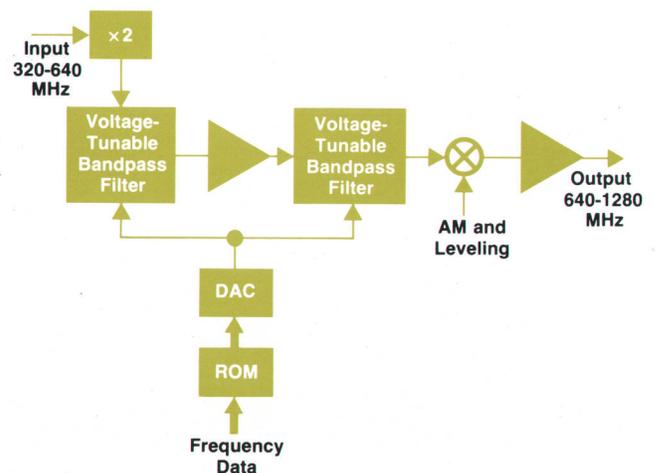
The three frequency bands converge at a PIN diode multiplexer. Multiplexing before the single output amplifier maintains fast frequency switching speed with low-level switching. Using only one output amplifier makes it easier to keep RF radiation low and junction temperatures down for high reliability.

The 17-dB gain, 10-kHz-to-1280-MHz output amplifier is a two-stage feedback amplifier using interstage mismatching realized on a sapphire thin-film substrate (Fig. 3). The substrate is mounted in an aluminum package which is attached to the instrument's frame for removal of heat from the transistor junctions.

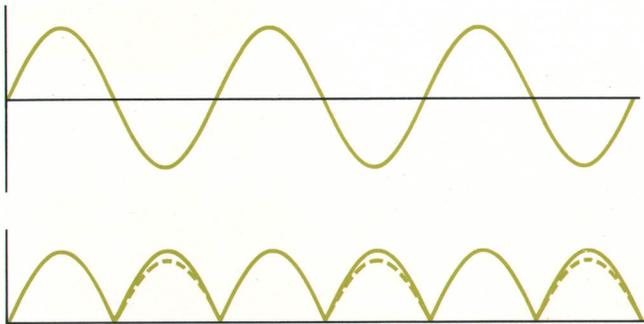
Since the use of negative supplies with emitter bypassing is difficult over such a wide band, a single power supply (+20V) is used. A special bias supply stage was developed to keep the bias points stable without appreciably loading

the signal line. This stage is shown in Fig. 3 as bias supply #2. Bias supply #1 in Fig. 3 is the same circuit without the noise shunt.

The bias stage operation is as follows. Emitter follower Q2 monitors the heavily filtered dc voltage at point A. This voltage is compared with the base bias voltage of Q3 causing the collector current of Q3 (which is the base current of



**Fig. 4.** Frequency doubler system provides the top octave of the 8662A frequency range.



**Fig. 5.** When a full-wave diode rectifier is used as a frequency doubler, mismatches between the positive and negative sides of the circuit can cause an imbalance (dotted line) and subharmonic components in the output.

the RF transistor) to vary. The varying RF transistor base bias causes the collector current to change, resulting in a change of voltage at point A. The negative feedback of this loop causes the collector voltage of the RF transistor to be stabilized and determined by a resistor divider.

The RF choke inside the microcircuit cannot remain a high enough impedance for output frequencies below 20 MHz. For this reason, a quasi-choke is formed using Q1. At dc the circuit is an emitter follower and causes the dc collector current of the RF device to be fixed by the base bias voltage of Q1 and the stabilized voltage at point A. At frequencies where capacitor C1 has a low reactance, the emitter and base voltages are driven in phase by any voltage applied at the emitter. This causes the impedance seen looking into the emitter to be high and determined by the base biasing resistors of Q1.

The level of the RF is monitored by a peak detector formed by D1 and C2. However, a peak detector sampling the output of a broadband amplifier can cause a problem. The  $1/f$  noise corner of high-performance RF transistors can extend to 100 kHz. When the peak detector samples the RF carrier, it also samples the  $1/f$  noise. The noise in the output of the detector is then modulated onto the RF carrier by the leveling loop. For output frequencies above 1 MHz this problem is greatly reduced by switchable noise shunts, which short the  $1/f$  noise to ground, preventing its being sampled by the detector.

## Frequency Doubler System

The top octave of the output frequency range of the 8662A is provided by an internal doubler. The complete doubler system is illustrated in Fig. 4.

The first stage is an active frequency doubler driven at a constant level. Two voltage-tunable bandpass filters follow, separated by an amplifier. The filters reject the harmonics and subharmonics present at the output of the doubler. A modulator (current-controlled attenuator) is next, controlled by the AGC loop to provide AM and leveled RF at the output. The final amplifier compensates for the loss of the modulator.

The read-only memory (ROM) contains the tuning voltage-versus-frequency data for the voltage-tuned filters. This information is sent to the digital-to-analog converter (DAC) which in turn provides the tuning voltage to the filters.

## Active Frequency Doubler

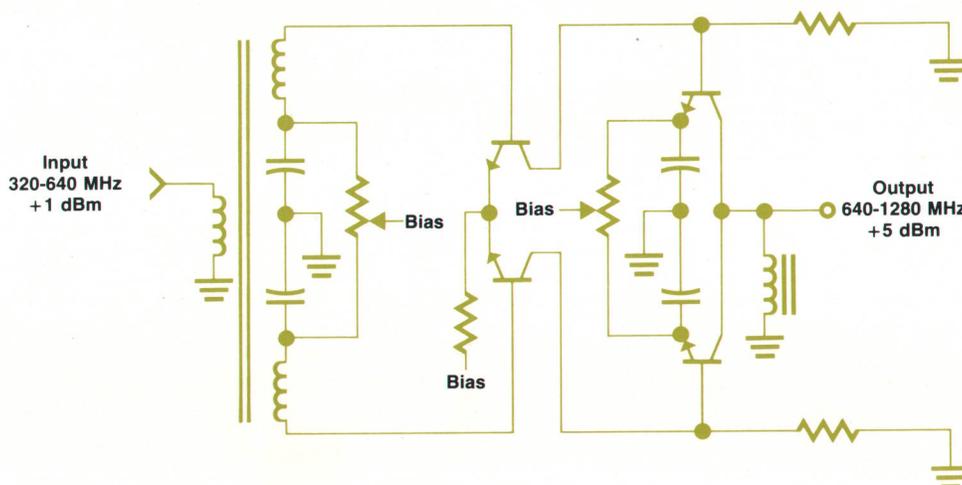
Diodes connected as a full-wave rectifier are commonly used as frequency doublers. The positive and negative half cycles of the doubler's input waveform appear at the output with the same polarity (see Fig. 5).

If the diodes or the sections of the drive transformer in the conduction paths of the positive and negative half cycles are not matched, the output cycles caused by the positive input half cycles will not match those caused by the negative input half cycles (dotted line in Fig. 5). This introduces in the output a signal whose fundamental is one-half the output frequency and contains harmonics at three halves, five halves, etc. of the output frequency, that is, subharmonics of the output frequency. Typically, the lower-order subharmonics are 20 dB below the output frequency in a diode doubler.

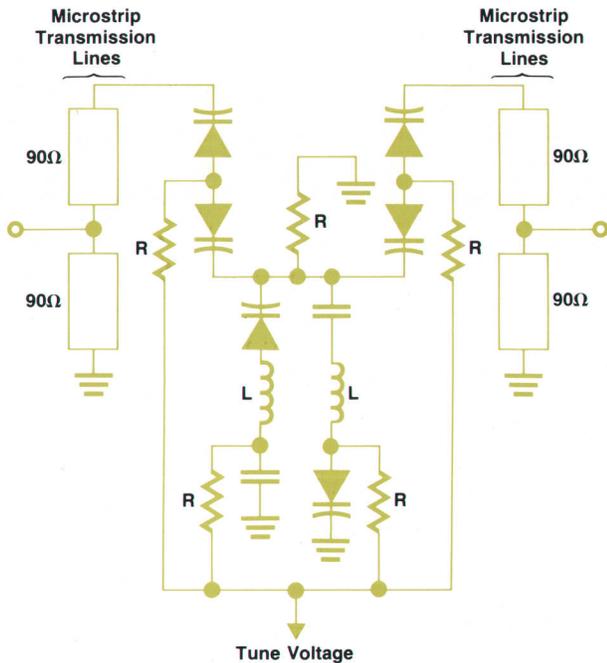
An input signal with even-order harmonic distortion will cause similar effects at the output. For example, the ratio of the one-half subharmonic to the doubled frequency is six dB higher than the ratio of the second harmonic to the fundamental at the input.

In a lossless doubler, the power at the doubled frequency is 7.4 dB below the input power, with the rest of the power appearing at dc and harmonics of the doubled frequency.

To obtain better balance (therefore lower subharmonics), and gain rather than loss, an active doubler circuit using



**Fig. 6.** Active doubler provides better balance and lower subharmonics than a diode rectifier. It also provides gain instead of loss.



**Fig. 7.** Voltage-tunable bandpass filter consists of two resonators coupled by a shunt capacitance. The tuning voltage changes the capacitance of the diodes.

monolithic transistor pairs was designed (Fig. 6).

The input transformer provides balanced differential drive to the differential transistor pair on the left. This pair, along with the adjustable base bias, provides a well balanced drive to the second pair, connected as a push-push doubler. The adjustable emitter bias corrects any residual imbalance. The subharmonic is typically 30 dB below the doubled frequency. The output power is about 5 dBm for a 1-dBm input.

#### Voltage-Tunable Bandpass Filter

The voltage-tuned bandpass filter consists of two resonators coupled by a shunt capacitance (Fig. 7). The filter is a thin-film circuit on sapphire. The transmission lines at the input and output are 90-ohm microstrip lines.

The capacitance of the diodes changes by a factor of four over the range of the tuning voltage, allowing the filter to tune over an octave. The shunt diodes keep the coupling constant between the two resonators such that bandwidth is proportional to the center frequency.

The inductance in series with the shunt coupling diodes is selected to series-resonate at 1.5 times the center frequency. This produces a notch that tracks the three-halves subharmonic and hence increases rejection at that frequency.

RF voltage across the tuning diodes modulates the capacitance and can result in harmonic generation. To minimize this effect, the diodes are used in pairs and placed in opposite directions. The RF voltage appearing across each diode pair tends to cause one diode to increase in capacitance and the other to decrease. The net effect is a much smaller variation in capacitance compared to a single diode, thereby minimizing harmonics.

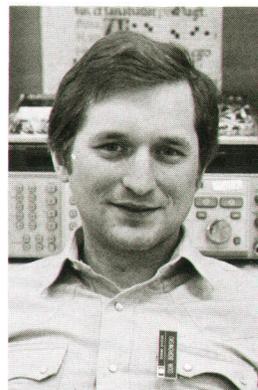
Note that all of the resistors in Fig. 7 are for providing the

tuning voltage to the diodes. Thus they are not RF circuit elements.

#### Acknowledgments

We wish to thank Roger Graeber who contributed greatly to the realization of the RF circuits and development of individual components in the output section.

#### Donald T. Borowski



Don Borowski was born in Pulaski, Wisconsin. He attended the University of Wisconsin at Madison for two years, spent a year at the Instituto Tecnológico y de Estudios Superiores de Monterrey, Mexico, and then returned to the University of Wisconsin, receiving his BSEE degree in 1973 and his MSEE in 1975. For his master's research project, he spent two months in Antarctica. He joined HP in 1975 and did RF and analog design for the 8662A Signal Generator output section. Now with HP's Spokane, Washington Division, he's a member of IEEE and NSPE. His

interests include vocal performance, mainly Gregorian chant and Renaissance polyphony, bicycling, collecting vintage electronics, and building an Italian virginal (a harpsichord). Don says that during his five years in California he never owned an automobile, but now in Spokane, alas, a car has become a necessity.

#### David L. Platt



Dave Platt is a native of Madison, Wisconsin. He attended the University of Wisconsin, receiving his BSEE degree in 1971 and his MSEE degree in 1972. With HP since 1972, he's served as a design engineer for the 8542B Automatic Network Analyzer and as project engineer for the output section of the 8662A Signal Generator. He's now a project manager with HP's Spokane, Washington Division. Dave is married, has two sons and lives in Veradale, Washington. His interests include home computing, amateur radio, and building radio-controlled cars.

# SPECIFICATIONS

## HP Model 8662A Synthesized Signal Generator

### FREQUENCY

RANGE: 10 kHz to 1280 MHz (1279.9999998 MHz).

RESOLUTION: 0.1 Hz (0.2 Hz above 640 MHz).

ACCURACY AND STABILITY: Same as reference oscillator.

### REFERENCE OSCILLATOR

INTERNAL: 10 MHz quartz oscillator. Aging rate  $<5 \times 10^{-10}$ /day after 10 day warm-up (typically 24 hr in normal operating environment).

### SPECTRAL PURITY

RESIDUAL SSB PHASE NOISE IN 1 Hz BW ( $320 \leq f_c < 640$  MHz):

Offset from carrier	10 Hz	100 Hz	1 kHz	10 kHz	100 kHz
SSB phase noise in 1 Hz BW (CW and AM mode)	-100 dBc	-112 dBc	-121 dBc	-131 dBc	-132 dBc

SSB BROADBAND NOISE FLOOR IN 1 Hz BW AT 3 MHz OFFSET FROM CARRIER:  $<-146$  dBc for  $f_c$  between 120 and 640 MHz at output levels above +10 dBm.

SPURIOUS SIGNALS:

	Frequency range (MHz)				
	0.01 to 120	120 to 160	160 to 320	320 to 640	640 to 1280
Spurious non-harmonically related	-90 dBc	-100 dBc	-96 dBc	-90 dBc	-84 dBc
Sub-harmonically related ( $\frac{f}{2}, \frac{3f}{2}$ , etc.)	none	none	none	none	-75 dBc
Power line (50-60 Hz) related and microphonically generated (within 300 Hz)	-90 dBc	-85 dBc	-80 dBc	-75 dBc	-70 dBc
Harmonics	$<-30$ dBc				

### OUTPUT

LEVEL RANGE: +13 to -139.9 dBm (1 V to 0.023  $\mu V_{rms}$  into 50  $\Omega$ ).

RESOLUTION: 0.1 dB.

LEVEL ACCURACY AND FLATNESS: Note that the 8662A uses microprocessor correction to achieve  $\pm 1$  dB absolute output level accuracy between +13 and -120 dBm. Correction is not available in the sweep mode. Correction can be defeated via a special keyboard function.

ABSOLUTE LEVEL ACCURACY:  $\pm 1$  dB between +13 and -120 dBm ( $+15^\circ$  to  $+45^\circ C$ ).  $\pm 3$  dB between -120 and -130 dBm. Includes flatness, attenuator error, detector error and measurement uncertainty.

FLATNESS (referenced to 100 MHz without correction down to -120 dBm): To 640 MHz,  $\pm 1.5$  dB; to 1280 MHz,  $\pm 3.5$  dB.

### AMPLITUDE MODULATION

DEPTH: 0 to 95% at output levels of +8 dBm and below (+10 dBm in uncorrected mode). AM available above these output levels but not specified.

RESOLUTION: 1%, 10 to 95% AM; 0.1%, 0 to 9.9% AM.

INCIDENTAL PM (at 30% AM): 0.15-640 MHz,  $<0.12$  radians peak; 640-1280 MHz,  $<0.09$  radians peak.

INCIDENTAL FM (at 30% AM): 0.15-640 MHz,  $<0.12 \times f_{mod}$ ; 640-1280 MHz,  $<0.09 \times f_{mod}$ .

INDICATED ACCURACY:  $\pm 5\%$  of reading  $\pm 1\%$  AM. Applies for rates given in table below, internal or external mode, for depths  $\leq 90\%$ .

RATES AND DISTORTION WITH INTERNAL OR EXTERNAL MODULATING SIGNAL:

Frequency range	AM rate	AM distortion		
		0-30% AM	30-70% AM	70-90% AM
0.15-1 MHz	dc-1.5 kHz	2%	4.0%	5.75%
1-10 MHz	dc-5 kHz	2%	4.0%	5.75%
10-1280 MHz	dc-10 kHz	2%	4.0%	5.75%

### FREQUENCY MODULATION

FM RATES (1 dB bandwidth): External ac, 20 Hz to 100 kHz; external dc, dc to 100 kHz.

### FM DEVIATION:

Center frequency (MHz)	Maximum peak deviation	
	ac mode (kHz)	dc mode (kHz)
0.01-120	the smaller of 100 or $f_{mod} \times 500$	100
120-160	25 or $f_{mod} \times 125$	25
160-320	50 or $f_{mod} \times 250$	50
320-640	100 or $f_{mod} \times 500$	100
640-1280	200 or $f_{mod} \times 1000$	200

INDICATED FM ACCURACY:  $\pm 8\%$  of reading plus 10 Hz (50 Hz to 20 kHz rates).

FM RESOLUTION: 100 Hz for deviations  $<10$  kHz, 1 kHz for deviations  $>10$  kHz.

INCIDENTAL AM (AM sidebands at 1 kHz rate and 20 kHz deviation):  $<-72$  dBc,  $f_c < 640$  MHz;  $<-65$  dBc,  $f_c \geq 640$  MHz.

FM DISTORTION:  $<1.7\%$  for rates  $<20$  kHz,  $<1\%$  for rates  $<1$  kHz.

CENTER FREQUENCY ACCURACY AND LONG TERM STABILITY:

ac mode: same as CW mode.

### DIGITAL SWEEP FUNCTIONS

START-STOP SWEEP: Sweeps between two selected frequencies.

SPAN SWEEP: Symmetrical sweep about center frequency selected.

SWEEP WIDTH: Determined by frequency resolution and frequency range of instrument; i.e., 0.1 Hz to 1280 MHz.

STEP SIZE: Choice of 100 or 1000 points per sweep, or settable to any value within the frequency resolution of the instrument.

SWEEP SPEED: Five selectable speeds: 0.5 ms, 1 ms, 2 ms, 10 ms and 100 ms per step. (0.5 ms is nominal value which will vary depending on use of markers or log sweep.)

LOG SWEEP: Two choices available in increasing steps of 10% or 1% of the last frequency.

FREQUENCY MARKERS: Five digital markers. Resolution and accuracy same as RF output.

INTENSITY MARKERS: Z axis modulation of CRT display.

AMPLITUDE MARKERS: Rear-panel signal (5 kHz triangle wave) can be applied to AM input connector to provide adjustable amplitude markers.

MARKER SWEEP: Start/stop sweeps between any two frequency markers can be selected.

DISPLAY BLANKING: 250  $\mu s$  positive pulse (TTL levels) available at rear panel for display blanking during frequency switching.

SWEEP OUTPUT: 0 to 10 V nominal stepped ramp. Zero at start of sweep; approximately +10 V at end of sweep regardless of sweep width. 10,000 points maximum.

### DIGITAL SWEEP MODES

AUTO: Sweep repeats automatically.

SINGLE: Single sweep activated by front panel keyboard.

MANUAL: Sweep controlled by front panel knob.

### REMOTE PROGRAMMING

INTERFACE: HP-IB (Hewlett-Packard's implementation of IEEE Standard 488).

FUNCTIONS CONTROLLED: All functions controlled from the front panel with the exception of the line switch are programmable with the same accuracy and resolution as in manual mode.

### REAR PANEL AUXILIARY CONTROL CONNECTOR

CONNECTOR: 14-pin.

FUNCTIONS CONTROLLED:

STEP UP/STEP DOWN: Same as increment keys on keyboard.

STOP SWEEP: Puts sweep in manual mode.

CONTINUE SWEEP: Puts sweep in auto mode.

SINGLE SWEEP: Initiates single sweep.

SEQUENCE: Same as sequence key on keyboard.

INPUT REQUIRED: Contact closure to ground or 5  $\mu s$  negative-true TTL pulse. Internally installed jumper determines mode.

OUTPUTS: 5  $\mu s$  negative-true TTL pulse output under following conditions: 1) change in signal parameter (for example frequency, amplitude, modulation). 2) end of sweep.

### OPERATING TEMPERATURE RANGE: 0° to +55°C.

LEAKAGE: Meets radiated and conducted limits of MIL STD 461A methods RE02 and CE03 as well as VDE 0871. Furthermore, less than 1  $\mu V$  is induced in a two turn, 1 inch diameter loop 1 inch away from the front panel and measured into a 50 ohm receiver.

POWER REQUIREMENTS: 115 (90 - 126) V or 230 (198 - 252) V; 48 to 66 Hz; 420 VA max.

WEIGHT: Net 30 kg (65.5 lb); shipping 36 kg (80 lb).

### PRICES IN U.S.A.:

8662A Synthesized Signal Generator, \$29,000.

11714A Service support kit (required for service), \$500.

11721A Frequency Doubler for operation to 2.56 GHz, \$285.

### MANUFACTURING DIVISION: STANFORD PARK DIVISION

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# Product Design for Precision and Purity

by Robert L. DeVries

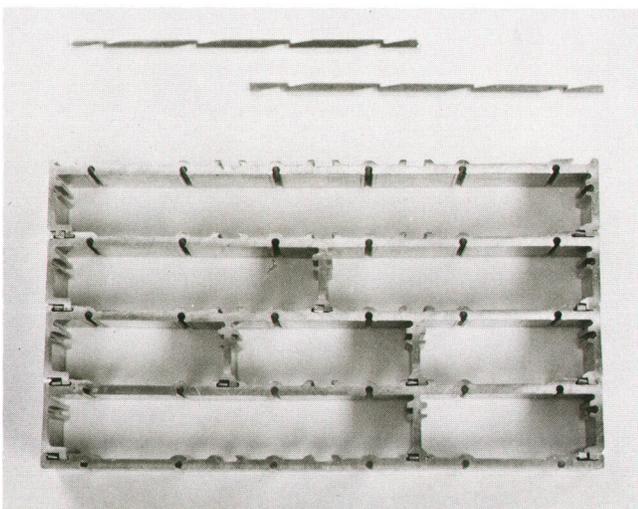
**I**N AN INSTRUMENT of the complexity of the 8662A Synthesized Signal Generator, the circuit design is of the utmost importance in achieving a signal of precision and purity to the degree specified. Much careful thought and sophisticated engineering went into the circuit design of the various modules. To provide the proper environment for these complex circuits to perform to expectations under various environmental conditions, a lot of care also went into the product design of the 8662A.

Some of the items given special attention were shielding, modularity, grounding, decoupling, reliability, power consumption, serviceability, human factors, and environmental testing.

## Shielding and Modularity

A frequency synthesizer has the general characteristic of having many frequencies present at one time in the various modules. Under some conditions of modulation and/or sweeping these many frequencies are rapidly changing. Unless a good job of shielding, decoupling, and isolation is achieved, there will be some unwanted frequencies at the output along with the desired frequency.

We wanted a shielding system that would give us the necessary shielding, low cost, and a modular approach. As the circuit design evolved we wanted to be able to adjust the volume of the shielded compartments to get maximum use of space without great expenditures in tooling for die-casting changes. As a result we designed a family of interlocking extrusions (Fig. 1). These include full-width, half-width, three-thirds, one-third/two-thirds, and end-plate extrusions. These may be assembled in any combination to best suit the circuit designers' needs and optimize board layout requirements.

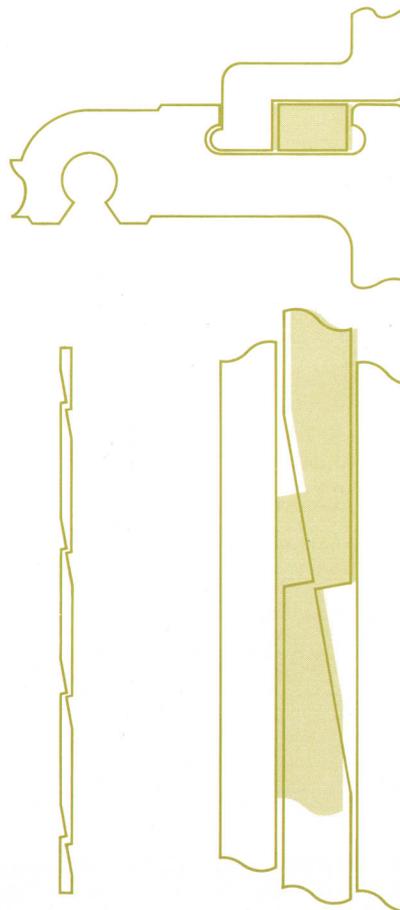


**Fig. 1.** Interlocking extrusions provide a low-cost modular approach to internal shielding in the 8662A Synthesized Signal Generator.

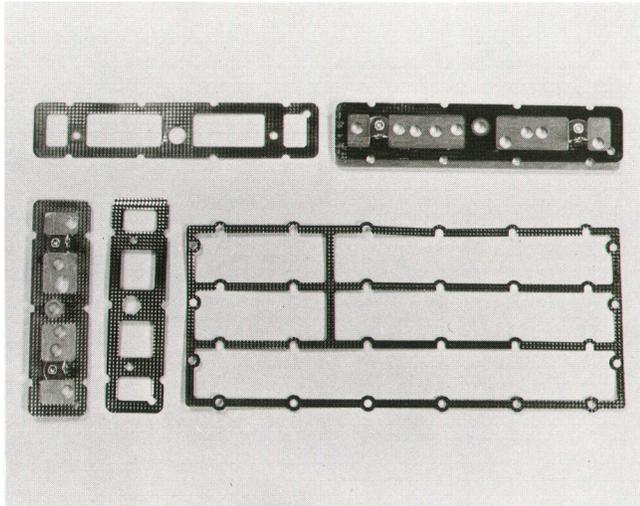
To seal the gaps where the extrusions interlock, we designed a shearing wedge that is inserted into an opening in the extrusion (Fig. 2). Pressure is applied to both ends of the wedge. It shears, wedges, and seals the joint at the extrusion interface. The shielding effectiveness at this joint is as good as if it were cast.

The shielding is further enhanced by using a ground plane on the extrusion side of the motherboard. On assemblies that have greater potential for leakage and radiation the motherboards are multilayer with a ground plane on the extrusion side, a ground plane on the other side, and dc and logic traces sandwiched between.

Along the edges of the extrusions we have a screw every 30 mm to minimize the gap length between the screws and reduce the possibility of leakage from the extrusions. To further minimize leakage we have included copper waffled gaskets at the interfaces between the extrusion covers and the extrusions, and between the extrusions and the motherboards to compensate for any irregularities at these inter-



**Fig. 2.** Shearing wedge seals the gaps where extrusions interlock.



**Fig. 3.** Copper waffled gaskets seal the interfaces between the extrusions and the extrusion covers and motherboards.

faces (Fig. 3).

The motherboards and extrusions covers are extra thick to make them stiff and eliminate any tendency to bow and create gaps between the extrusion screws.

### Grounding and Decoupling

In general, the high-frequency signals are routed by coaxial cable to the various circuits and connected at the top cover connectors. The low-frequency or dc signals are routed by means of multiconductor cables or motherboards. The more critical or sensitive plug-in boards get additional grounding by means of spring ground straps secured to two edges of the plug-in boards, which insert into the grooves in the extrusions (Fig. 4). These ground straps provide two important benefits. First they give us an intimate grounding scheme between the plug-in board ground plane and the extrusion wall. Next, they provide a very effective thermal path to carry the heat away from the board, to the extrusion, and then to the outside.

The RF and dc portions of the plug-ins are shielded and decoupled from each other by means of a beryllium-copper shield on the connector end of the board, which covers the decoupling network, surrounds the interface connector, and grounds the shield to the motherboard ground plane when the board is inserted (Fig. 4).

### Reliability

Reliability was foremost in our minds throughout the project. High component temperatures generally mean high failure rates. To insure a lower operating temperature we have a cooling system that pulls air in through the rear panel, builds up a pressure through the center of the 8662A to force the air through and around the extrusions, and exhausts out the perforated side covers. The air cooling the power supply comes in the rear, goes past the heat sinks, and exhausts out the perforated side cover.

To insure reliable operation at any combination of line voltage and line frequency we selected a fan that would provide adequate air flow with minimum vibration and

noise. To minimize phase noise we gave careful consideration to the vibrations caused by the fan. We shock mounted the fan, the crystal reference, and the crystal filters that are sensitive to vibration. We provide thermal isolation and baffling to the reference oscillator. We intentionally do not cool the oven, since this would waste power and make control of the oven temperature more difficult. To reduce the power dissipated in the 8662A we are using a switching-regulated power supply. A thermal cutout in the power supply turns the instrument off in case of a fan failure or if the temperature gets too high.

Reliability is further insured by using prescreened semiconductors and a more efficient power supply, derating of components, and careful thermal profile evaluation.

### Serviceability

In addition to reliability, serviceability got special attention as the product was being developed. For such a complex instrument, the 8662A is easy to service. In addition to the error codes on the front panel and the internal loop-unlocked lights, all the plug-in boards are accessible from the top, test points are provided, extender boards are available, and the front panel pulls out and tilts down for access to the attenuator, filter, and panel components.

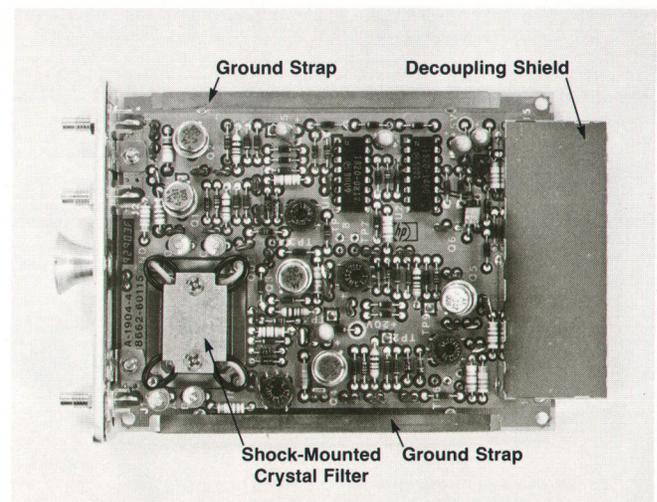
The motherboards are in one plane, clearly marked, and very accessible. The major assemblies are removable with a minimum of effort. Each assembly is mechanically independent. The operating and service manual that accompanies the instrument is thorough, complete and comprehensive.

The rear-panel covers are easily removed for access to the power components, fan, VCO, and reference oscillator. Sturdy rear feet are provided for the user who wishes to operate the instrument standing vertically.

### Human Factors

The front panel is designed for ease of operation. The sweep and marker functions are on the far left.

Function, data, and increment keys are in the center sec-



**Fig. 4.** Spring ground strap provides additional grounding for sensitive or critical boards. A beryllium-copper shield decouples the RF and dc circuits.

tion. This section is used most often and is tilted to provide a more natural feel for the user. The connectors are on the far right to keep cables away from the keyboard area. Generally, the operating parameters are input working from left to right across the keyboard.

The rotary pulse generator (large knob on the right) has been included for those users who still like to tune a signal source by turning a knob.

### Environmental Testing

The completed instrument is rugged and strong and has gone through repeated vibration, shock, and package drop tests. The tests have included temperature and humidity, environmental extremes, radiated and conducted interference, magnetic radiation and susceptibility tests and many other tests. The switching power supply went through several hundred hours of life tests, on/off cycling, high/low line operation, shorted outputs to ground, shorted outputs to each other, overvoltage and overcurrent testing. The objective of all of this testing and careful design is an instrument that should give the user years of trouble-free service.

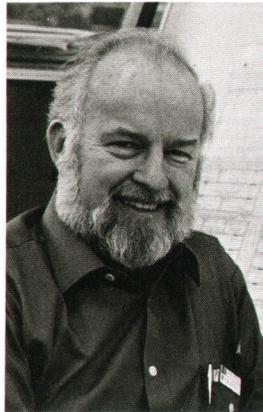
### Acknowledgments

Throughout the development of the 8662A there have been enthusiastic support and contributions from many departments here at HP. While it's difficult to name all those involved I want to thank them all for their support. Specifically I want to thank Dan Derby, Jim Stewart, and Lynn Beckley for their excellent front-panel marking, layout, and design, Betty Dodson and her coworkers for the careful detailing and layout of the 78 etched circuit boards

in the 8662A, Bill West for his well engineered, reliable pushbutton switch which was designed for this product but because of its size, convenience, and reliability is used on many HP products, and Bob Guisto, John Ellis, Walt Weightman and Kress Alexander for their contributions in tool design, extrusion design, wedge design and shielding investigations. Accurate product documentation and pre-production part procurement are the results of efforts of Ruby Miller, Myra Slade, Mary Richards, Bob Cirner, and Hans Voorby. A special thanks to Shirley Flock and Edna Fleck who provided us with many excellent suggestions to improve manufacturability and reliability.

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### Robert L. DeVries



Bob DeVries joined HP's test department in 1956, after serving as a U.S. Air Force radar technician for four years and a salesman for three more. In 1959 he became a product designer, and in the next 22 years helped design an impressive array of HP oscilloscopes, tape systems, and microwave products, the latest being the 8662A Signal Generator. He is named inventor on a connector switch patent. Bob was born in Spokane, Washington. He's married, has two children, and lives in Palo Alto, California. He enjoys photography, electronics, high-fidelity systems, woodworking, and bicycling.

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## Verifying High Spectral Purity and Level Accuracy in Production

by John W. Richardson

**A** PERPLEXING SITUATION usually exists with the introduction of a new, state-of-the-art product such as the 8662A Synthesized Signal Generator. How does one test, with sufficient margin, the various critical performance specifications without losing production line efficiency?

For the 8662A, two critical specifications are spectral purity and output level accuracy. In both cases no existing equipment is available to measure these parameters efficiently with acceptable measurement error. Spectral purity (phase noise and spurious) is difficult to measure without a suitable low-noise receiver to resolve low-level signals near the carrier. Output level accuracy presents a problem because of difficulty in accurately measuring RF power over a 150-dB range. The solution to these measurement prob-

lems, along with the solutions for most other signal generator specification measurement problems, has taken the shape of the HP-IB test system shown in Fig. 1.

Measurement of spectral purity requires a spectrally clean, low-noise receiver or spectrum analyzer with noise performance at least equal to that typical of the 8662A. Existing spectrum analyzers have noise performance about 20 dB worse than the 8662A for offsets less than 100 kHz and require a 30-Hz bandwidth to measure the 90-dB spurious specification with sufficient signal-to-noise ratio. Measurement of very low output power levels also requires a receiver or spectrum analyzer with a sensitive, low-noise input. Such a receiver has been incorporated in the HP-IB test system.

The heart of this distributed test system and the key to

making spectral purity measurements is the local oscillator. The LO establishes the receiver noise floor and is a potential source of internally generated spurious signals. Another 8662A fulfills this low-noise, low-spurious need. For spectral purity measurements, the receiver input is a high-level mixer whose output can be routed through various paths to a multiplexer, which selects one of three pieces of measurement gear. RF input signals are routed using semirigid coaxial cable and switching is done using 8761A Micro-wave Switches. Impedance discontinuities associated with the input are almost insignificant. Post-mixer routing is done with flexible triple-shielded coaxial cable and switching is done with lower-frequency coaxial relays.

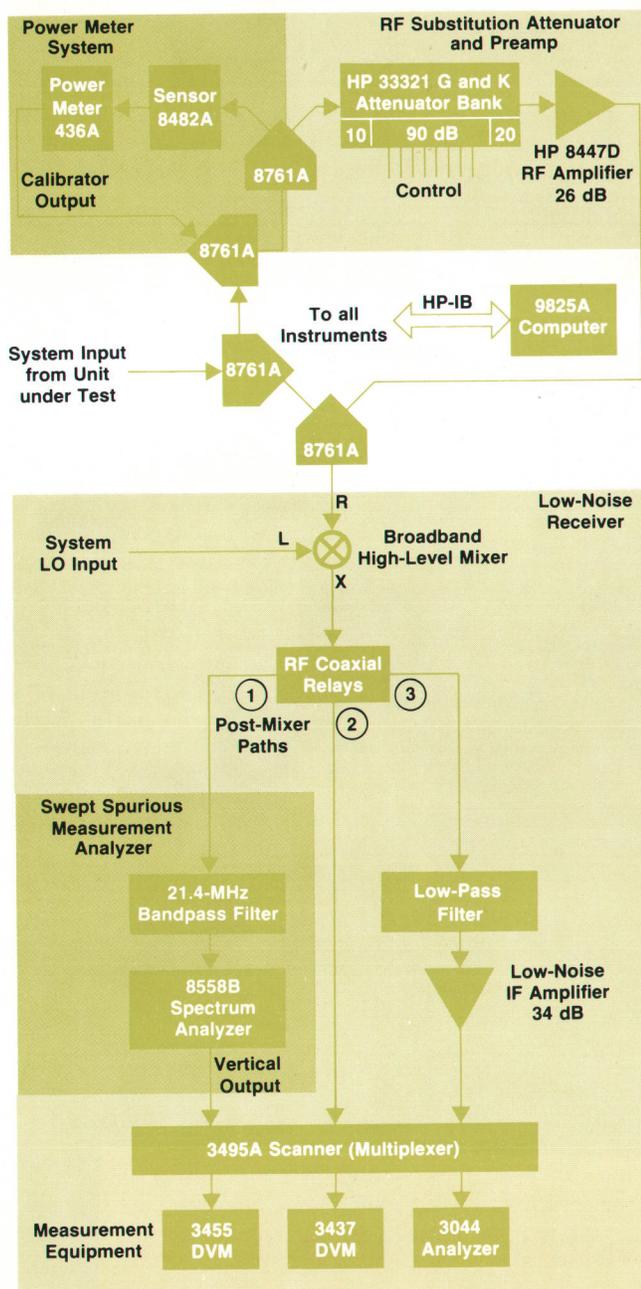


Fig. 1. 8662A performance is tested in production by this HP-IB (IEEE 488) test system.

11) RF = 639.9000000 MHz  
Residual Measurement

Freq. (Hz)	Level (dbc)	Spec.	Type	
10.0	-109.03	-102.00	Noise	Passed
100.0	-123.33	-115.00	Noise	Passed
975.0	-131.99	-125.38	Noise	Passed
1975.0	-132.00	-128.49	Noise	Passed
9950.0	-139.00	-135.58	Noise	Passed
99000.0	-138.32	-136.20	Noise	Passed
95000.0	-135.72	-135.15	Noise	Passed
195000.0	-138.18	-135.68	Noise	Passed
395000.0	-138.93	-136.29	Noise	Passed
795000.0	-142.90	-136.30	Noise	Passed
995000.0	-146.09	-136.30	Noise	Passed

Test Passed

Fig. 2. Typical phase noise measurement results produced by the system of Fig. 1.

The system mixer is used as a phase detector when measuring phase noise by adjusting the relative phases of the two inputs to a quadrature relationship. The 3495A Scanner connects the mixer output directly to the 3437A DVM. Phase shifting is accomplished by incrementing the local oscillator 0.2 Hz for an appropriate period of time while the 3437A and the 9825A continuously monitor the mixer output. When the mixer output approaches 0V within acceptable limits, the computer signals the LO to decrement 0.2 Hz, causing the mixer output to be fixed at this voltage. (The 8662A is phase-continuous when switching the least-significant six digits.) Now the mixer output is switched to path three and the tracking spectrum analyzer (HP 3044A) is selected as the measurement instrument. Phase noise is characterized at offsets from 10 Hz to 1 MHz for each of 13 different carrier frequencies, thoroughly checking all 8662A internal signal paths.

Measurement accuracy of this system is enhanced in several ways. First, since phase noise is specified as a ratio with respect to the carrier, the carrier level is measured, effectively calibrating out frequency-dependent mixer conversion loss and system insertion loss. Second, since analyzer noise characteristics differ from sine wave characteristics, calibration factors for analyzer Gaussian random noise response are loaded into the program. (These factors are discussed in HP Application Notes #207 and #150-4.) Third, since the mean value of a random process is desired, some amount of averaging must be done. Depending on what IF bandwidth is used in the 3044A, enough independent analyzer readings are taken so that there is about a 70% confidence that the mean value is known within  $\pm 0.32$  dB. This numerical averaging results in a post-detector bandwidth of approximately 0.4 Hz. A printout showing the results of an actual noise measurement at a 639.9-MHz carrier frequency is shown in Fig. 2.

A second critical aspect of spectral purity is spurious content.\* Although some calibration factors associated with input mixer frequency response and spectrum analyzer nonlinearity are loaded into the computer program, the primary measurement advantage here is one of high speed without sacrificing confidence. High speed is achieved by using wide bandwidths and high confidence is achieved by performing swept spectral analysis rather than spot measurements.

\*See page 20 for further discussion of spurious measurement.

#	FREQUENCY (MHz)		SWP CF	SPUR MECHANISM	LEVEL (dBc)	
	8662A CF	LO CF			SPEC	MEAS
110	200.000000	221.315000	-0.085	20.40kHz	-98	-101.3
111	500.000000	521.485000	0.085	20.40kHz	-93	-99.1
112	500.000000	521.315000	-0.085	20.40kHz	-93	-99.6
113	1000.000000	1021.485000	0.085	20.40kHz	-86	-95.4
114	1000.000000	1021.315000	-0.085	20.40kHz	-86	-95.2
115	497.133000	518.618000	0.085	120MHz+00	-93	-100.7
116	488.550000	510.035000	0.085		-93	-100.1
117	503.300000	524.785000	0.085	00+FM50	-93	-98.1
118	496.011000	517.436000	0.085	SV+R0	-93	-101.9
119	600.177100	621.662100	0.085	FV+NV	-93	-100.5
120	327.8000190	306.3150190	0.085		-93	-101.9
121	639.950000	618.465000	0.085	640+0.S.	-93	-100.7

**Fig. 3.** A partial printout of an 8662A test system spurious analysis. The far right column shows maximum spurious levels detected by the analyzer.

Referring to the test system block diagram, post-mixer path 3 is taken, with the analyzer vertical output digitized by the 3437A Sampling Voltmeter. The burst of readings is transmitted to a buffer register in the 9825A. Various correction factors are applied and the result is checked against specifications. Part of a spurious analysis is shown in Fig. 3.

Verifying the  $\pm 1$ -dB level accuracy specification down to  $-120$  dBm aptly demonstrates the leverage available with a computer-controlled test system over separate, non-systemized instruments. Because of the extremely wide dynamic range involved, two different groups of instruments are used. High levels are measured with an 8482A/436A Power Meter system, while low levels ( $< -15$  dBm) are measured in a variable-bandwidth receiver identical to the phase-noise receiver.

Accuracy of the high-level system is enhanced using three different techniques involving standards laboratory calibration. First, net system insertion loss is adjusted to 0 dB at 50 MHz. This is done by inserting a known power level and adjusting the 436A calibration control (hardware correction). Second, system frequency response is characterized and correction factors are loaded into the computer program. This is done by inserting a known power level over the frequency range of 0.1 to 1300 MHz (software correction). Third, the incremental attenuation for each 10-dB step of a 90-dB RF attenuator bank is measured and loaded into the computer program. These known attenuation factors are used in a transfer method to calibrate the 3044A Spectrum Analyzer over most of its dynamic range (software correction).

Absolute level calibration and frequency response for the 3044A Analyzer are determined by comparing swept read-

ings from the lowest range on the power meter ( $-15$  dBm) to those taken at the same power setting on the analyzer and computing a difference correction factor for each frequency. At lower power settings, the receiver is expected to have unchanging frequency response and the level accuracy is determined from attenuation transfer. The 9825A generates new correction factors to compensate for the receiver's dynamic range nonlinearity before each measurement sequence.

It takes about one-half hour to perform the level transfer calibration and measure approximately 670 points for each 8662A on the production line. This process is repeated in the quality assurance area. Root sum squared measurement uncertainty for this measurement at  $-120$  dBm is  $\pm 0.22$  dB.

### Acknowledgments

This automatic test system has been conceived and implemented with contributions from many people at the Stanford Park Division. Rolly Hassun and Skip Crilly helped develop this initial concept. Bill Thomas, Lloyd Marugg, Greg Taylor, Charlie Sallberg and Jan Holler wrote much of the software. Brent Palmer from the standards lab set up periodic calibration procedures and helped derive the measurement error analysis. John Hasen provided helpful feedback and system control during the exhaustive environmental testing. Bob DeVries designed much of the interface box while Edna Fleck assembled many of the interconnect cables.

### John W. Richardson



John Richardson attended Kent State University and the University of California at Santa Barbara, graduating from the latter in 1973 with a BSEE degree. With HP since then, he's served as production engineer for the 8640B Signal Generator, the 436A Power Meter, and the 8662A Signal Generator. He's now a product marketing engineer with HP's Spokane, Washington Division. John is serious about running and also enjoys backpacking, photography, and skiing. He was born in Akron, Ohio and now lives in Spokane. He's married and has three children.

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